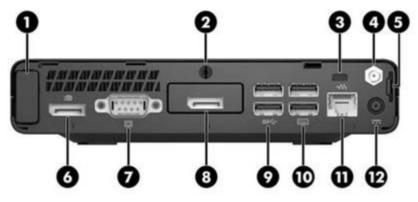
Overview

HP ProDesk 400 G3 Desktop Mini Business PC



- 1. USB 3.1 Gen 1 port
- 2. USB 3.1 Gen 1 charging port
- 3. Headphone connector

- 4. Universal Audio Jack with CTIA headset support
- 5. Hard drive activity light
- 6. Dual-state power button



- 1. Antenna cover
- 2. Cover lock switch
- 3. Cable lock slot
- 4. External antenna connector
- 5. Padlock loop
- 6. Dual-Mode DisplayPort? (DP++)

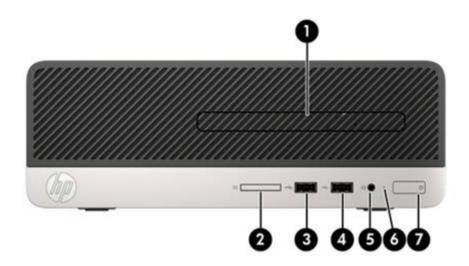
- 7. Serial port
- 8. Choice of port (DisplayPort?, HDMI, VGA or Serial)
- 9. (2) USB 3.1 Gen 1 ports (black)
- (2) USB 2.0 ports (black), allows for wake from S4/S5 with keyboard/mouse when connected and enabled in BIOS
- 11. RJ-45 network jack
- 12. Power connector

Not Shown

- Slots (1) internal M.2 2280 connector for optional wireless NIC
 - (1) internal M.2 SSD storage (2230 or 2280 connector)
- Bays (1) 2.5"? internal storage drive bay
- VESA Support for VESA 100 mounting system on bottom of PC chassis

Overview

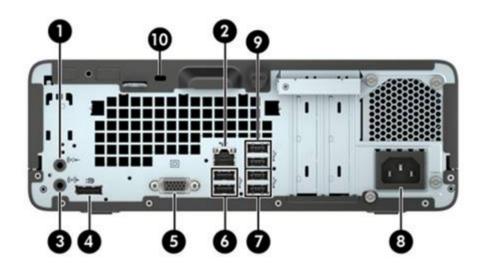
HP ProDesk 400 G4 Small Form Factor Business PC



- 1. Slim Optical Drive (optional)
- 2. SD card 3.0 reader (optional)
- 3. USB 3.1 Gen 1 port
- 4. USB 3.1 Gen 1 port

- 5. Universal Audio Jack with CTIA headset support
- 6. Hard drive activity light
- 7. Dual-state power button

HP ProDesk 400 G4 Small Form Factor Business PC



- 1. Audio-in connector
- 2. RJ-45 (network) jack
- 3. Audio-out connector
- 4. Dual-Mode DisplayPort? (DP++) connector
- 5. VGA monitor connector

- 6. (2) USB 2.0 ports (black), allows for wake from S4/S5 with keyboard/mouse when connected and enabled in BIOS
- 7. (2) USB 3.1 Gen 1 ports
- 8. Power cord connector
- 9. (2) USB 2.0 ports
- 10. Cable lock slot

NOTE: The serial port is no longer standard to the chassis. A serial port and PS/2 port PCIe combination are available.

Not Shown

Overview

Slots (2) PCI Express x16 graphics connector; one wired as an x4

(1) internal M.2 PCIe x1 connector for optional wireless NIC

Bays (1) 3.5"? internal storage drive bay or 2.5"? internal storage drive bay

(1) 9.5mm slim optical drive bay

HP ProDesk 400 G4 and 480 G4* Microtower Business PC

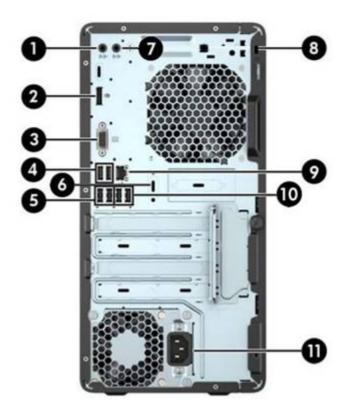


- 1. Slim Optical Drive (optional)
- 2. Dual-state power button
- 3. Hard drive activity light
- 4. Universal Audio Jack with CTIA headset support
- 5. (2) USB 3.1 Gen 1 ports
- 6. SD card 3.0 reader (optional)

HP ProDesk 400 G4 and 480 G4* Microtower Business PC

^{*480} G3 model not available in all regions.

Overview



- 1. Audio-out connector
- 2. Dual-Mode DisplayPort? (DP++) connector
- 3. VGA monitor connector
- 4. (2) USB 2.0 ports (black), allows for wake from S4/S5 with keyboard/mouse when connected and enabled in BIOS
- 5. (2) USB 3.1 Gen 1 ports
- 6. Optional serial port

- 7. Audio-in connector
- 8. Cable lock slot
- 9. RJ-45 (network) jack
- 10. (2) USB 2.0 ports
- 11. Power cord connector

NOTE: The serial port is no longer standard to the chassis and a serial port and second serial port and PS/2 port combination are available from HP.

*480 G3 model not available in all regions.

Not Shown

Slots

- (2) PCI Express x16 graphics connectors; one wired as an x4
- (1) PCI Express x1 accessory connector
- (1) internal M.2 PCIe x1 connector for optional wireless NIC

NOTE: 480 MT model will offer (1) PCI connector instead of (1) PCI Express x1 accessory connectors

Bays

- (1) 3.5"? internal storage drive bay or 2.5"? internal storage drive bay
- (1) 3.5"? internal storage drive bay
- (1) 9.5mm internal optical drive bay

AT A GLANCE

Overview

- Choice of four form factors: Desktop Mini, Small Form Factor, Microtower and All-in-One (touch and non-touch configurations available) (AiO available 2H 2017)
- New commercial design on 400 G4 MT, 400 G4 SFF and 400 G3 DM
- HP-developed and engineered UEFI BIOS supporting security, manageability and software image stability
- H270 chipset supporting both Intel®7th generation Core? processors and Intel® 6th generation Core? processors
- Integrated Intel® HD Graphics; optional discrete graphics option available for MT and SFF form factors
- Processor support up to 65W for MT/SFF and up to 35W for Desktop Mini
- Realtek RTL8111 HSH GbE LOM Network Connection (standard)
- DDR4 Synchronous Dynamic Random Access Memory (SDRAM)
- Standard and high efficiency energy saving power supply options
- ENERGY STAR certified models available
- EPEAT® Gold registered in the United States. Registration may vary by country. See http://www.epeat.net for registration status in your country.
- Arsenic-free
- Dust filter available for all platforms

NOTE: See important legal disclosures for all listed specs in their respective features sections.

OPERATING SYSTEMS

Preinstalled

Windows 10 Pro 641

Windows 10 Pro 64 (National Academic License)3

Windows 10 Home 641

Windows 10 Home Single Language 641

Windows 7 Professional 64 (available through downgrade rights from Windows 10 Pro)^{2, 4}

Windows 7 Professional 32 (available through downgrade rights from Windows 10 Pro)^{2, 4}

Pre-installed (other)

FreeDOS 2.0

NeoKylin Linux® 64

Web-supported only

Windows 10 Enterprise 641

Windows 7 Enterprise 644

- 1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.
- 2. This system is preinstalled with Windows 7 Pro software and also comes with a license and media for Windows 10 Pro software. You may only use one version of the Windows software at a time. Switching between versions will require you to uninstall one version and install the other version. You must back up all data (files, photos, etc.) before uninstalling and installing operating systems to avoid loss of your data.
- 3. Some devices for academic use will automatically be updated to Windows 10 Pro Education with the Windows 10 Anniversary Update. Features vary; see https://aka.ms/ProEducation for Windows 10 Pro Education feature information.
- 4. Only available with 6th generation (Intel) processors.

CHIPSET

Intel® H270

PROCESSORS*, **

*NOTE: Your product does not support Windows 8 or Windows 7, In accordance with Microsoft's support policy, HP does not support the Windows® 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows® 8

Overview

or Windows 7 drivers on http://www.support.hp.com

**NOTE: Multi-Core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. 64-bit computing system required. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering is not a measurement of higher performance.

Intel® 7th Generation Core? i7 Processors	400 G3 DM	400 G4 SFF	400 G4 MT	480 G4 MT
Intel® Core? i7-7700 Processor		Х	Х	Х
65W				
Up to 4.2 GHz Max. Turbo Frequency (3.6 GHz base				
frequency)				
8 MB cache, 4 cores, 8 threads				
Intel® HD Graphics 630				
Supports DDR4 memory up to 2400 MT/s data rate				
Intel® Core? i7-7700T Processor	x			
35W				
Up to 3.8 GHz Max. Turbo Frequency (2.9 GHz base				
frequency)				
8 MB cache, 4 cores, 8 threads				
Intel® HD Graphics 630				
Supports DDR4 memory up to 2400 MT/s data rate				

Intel® 7th Generation Core? i5 Processors	400 G3 DM	400 G4 SFF	400 G4 MT	480 G4 MT
Intel® Core? i5-7500 Processor		Х	Х	Х
65W				
Up to 3.8 GHz Max. Turbo Frequency (3.4 GHz base				
frequency)				
6 MB cache, 4 cores, 4 threads				
Intel® HD Graphics 630				
Supports DDR4 memory up to 2400 MT/s data rate				
Intel® Core? i5-7500T Processor	X			
35W				
Up to 3.3 GHz Max. Turbo Frequency (2.7 GHz base				
frequency)				
6 MB cache, 4 cores, 4 threads				
Intel® HD Graphics 630				
Supports DDR4 memory up to 2400 MT/s data rate				
Intel® Core? i5-7600 Processor		X	X	X
65W				
Up to 4.1 GHz Max. Turbo Frequency (3.5 GHz base				
frequency)				
6 MB cache, 4 cores, 4 threads				
Intel® HD Graphics 630				
Supports DDR4 memory up to 2400 MT/s data rate				
Intel® Core? i5-7600T Processor	X			
35W				
Up to 3.7 GHz Max. Turbo Frequency (2.8 GHz base				
frequency)				
6 MB cache, 4 cores, 4 threads				
Intel® HD Graphics 630				
Supports DDR4 memory up to 2400 MT/s data rate				

Intel® 7th Generation Core? i3 Processors

400 G3 DM 400 G4 SFF 400 G4 MT 480 G4 MT

Intel® Core? i3-7100 Processor

Overview				
51W 3.9 GHz base frequency 3 MB cache, 2 cores, 4 threads Intel® HD Graphics 630 Supports DDR4 memory up to 2400 MT/s data rate Intel® Core? i3-7100T Processor 35W 3.4 GHz base frequency	x			
3 MB cache, 2 cores, 4 threads Intel® HD Graphics 630 Supports DDR4 memory up to 2400 MT/s data rate		v	v	v
Intel® Core? i3-7300 Processor 51W 4.0 GHz base frequency 4 MB cache, 2 cores, 4 threads Intel® HD Graphics 630		X	X	X
Supports DDR4 memory up to 2400 MT/s data rate Intel® Core? i3-7300T Processor 35W 3.5 GHz base frequency 3 MB cache, 2 cores, 4 threads Intel® HD Graphics 630	x			
Supports DDR4 memory up to 2400 MT/s data rate Intel® Core? i3-7320 Processor 51W 4.1GHz base frequency 4 MB cache, 2 cores, 4 threads Intel® HD Graphics 630 Supports DDR4 memory up to 2400 MT/s data rate		x	x	x

Intel® 7th Generation Pentium® Processors	400 G3 DM	400 G4 SFF	400 G4 MT	480 G4 MT
Intel® Pentium® G4560 Processor		Х	X	Х
54W				
3.5 GHz Base Frequency				
3 MB cache, 2 cores, 4 threads				
Intel® HD Graphics 610				
Supports DDR4 memory up to 2400 MT/s data rate				
Intel® Pentium® G4560T Processor	X			
35W				
2.9 GHz Base Frequency				
3 MB cache, 2 cores, 4 threads				
Intel® HD Graphics 610				
Supports DDR4 memory up to 2400 MT/s data rate				
Intel® Pentium® G4600 Processor		X	X	X
51W				
3.6 GHz Base Frequency				
3 MB cache, 2 cores, 4 threads				
Intel® HD Graphics 630				
Supports DDR4 memory up to 2400 MT/s data rate				
Intel® Pentium® G4600T Processor	X			
35W				
3.0 GHz Base Frequency				
3 MB cache, 2 cores, 4 threads				
Intel® HD Graphics 630				
Supports DDR4 memory up to 2400 MT/s data rate				

<u> </u>		i i i obesk	100 05 511,	100 0 1111
verview				
Intel® Pentium® G4620 Processor		x	x	x
51W				
3.7 GHz Base Frequency				
3 MB cache, 2 cores, 4 threads				
Intel® HD Graphics 630				
Supports DDR4 memory up to 2400 MT/s data rate				
Intel® 7th Generation Celeron® Processors	400 G3 DM	400 G4 SFF	400 G4 MT	480 G4 MT
Intel® Celeron ® G3930 Processor		X	Х Х	X
51W				
2.9 GHz Base Frequency				
2 MB cache, 2 cores, 2 threads				
Intel® HD Graphics 610				
Supports DDR4 memory up to 2133 MT/s data rate				
Intel® Celeron ® G3930T Processor	×			
35W				
2.7 GHz Base Frequency				
2 MB cache, 2 cores, 2 threads				
Intel® HD Graphics 610				
Supports DDR4 memory up to 2133 MT/s data rate				
Intel® Celeron ® G3950 Processor		X	X	X
51W				
3.0 GHz Base Frequency				
2 MB cache, 2 cores, 2 threads				
Intel® HD Graphics 610				
Supports DDR4 memory up to 2133 MT/s data rate				
Intel® 6th Generation Core? i7 Processors	400 G3 DM	400 G4 SFF	400 G4 MT	480 G4 MT
Intel® Core? i7-6700 Processor		X	X	X
65W				
Up to 4.0 GHz Max. Turbo Frequency (3.4 GHz base				
frequency)				
8 MB cache, 4 cores, 8 threads				
Intel® HD Graphics 530				
Supports DDR4 memory up to 2133 MT/s data rate				
Intel® Core? i7-6700T Processor	X			
35W				
Up to 3.6 GHz Max. Turbo Frequency (2.8 GHz base				
frequency)				
8 MB cache, 4 cores, 8 threads				
Intel® HD Graphics 530				
Supports DDR4 memory up to 2133 MT/s data rate				
Intel® 6th Generation Core? i5 Processors	400 G3 DM	400 G4 SFF	400 G4 MT	480 G4 MT
Intel® Core? i5-6500 Processor	-	Х	х	Х
65W				
Up to 3.6 GHz Max. Turbo Frequency (3.2 GHz base				
frequency)				
6 MB cache, 4 cores, 4 threads				
Intel® HD Graphics 530				
Supports DDR4 memory up to 2133 MT/s data rate				
Intel® Core? i5-6600T Processor	X			
35W				
Up to 3.5 GHz Max. Turbo Frequency (2.7 GHz base				
frequency)				

Overview

6 MB cache, 4 cores, 4 threads
Intel® HD Graphics 530
Supports DDR4 memory up to 2133 MT/s data rate
Intel® Core? i5-6500T Processor
35W
Up to 3.1 GHz Max. Turbo Frequency (2.5 GHz base frequency)
6 MB cache, 4 cores, 4 threads
Intel® HD Graphics 530

Supports DDR4 memory up to 2133 MT/s data rate

Supports DDR4 memory up to 2133 MT/s data rate

Intel® 6th Generation Core? i3 Processors	400 G3 DM	400 G4 SFF	400 G4 MT	480 G4 MT
Intel® Core? i3-6100 Processor	-	Х	Х	Х
51W				
3.7 GHz base frequency				
3 MB cache, 2 cores, 4 threads				
Intel® HD Graphics 530				
Supports DDR4 memory up to 2133 MT/s data rate				
Intel® Core? i3-6100T Processor	x			
35W				
3.2 GHz base frequency				
3 MB cache, 2 cores, 4 threads				
Intel® HD Graphics 530				
Supports DDR4 memory up to 2133 MT/s data rate				
Intel® 6th Generation Pentium® Processors	400 G3 DM	400 G4 SFF	400 G4 MT	480 G4 MT
Intel® Pentium® G4500 Processor		Х Х	X	Х
51W				
3.5 GHz Base Frequency				
3 MB cache, 2 cores, 2 threads				
Intel® HD Graphics 530				
Supports DDR4 memory up to 2133 MT/s data rate				
Intel® Pentium ® G4400 Processor		Х	X	X
54W				
3.3 GHz Base Frequency				
3 MB cache, 2 cores, 2 threads				
Intel® HD Graphics 510				
Supports DDR4 memory up to 2133 MT/s data rate				
Intel® Pentium® G4400T Processor	х			
35W				
2.9 GHz Base Frequency				
3 MB cache, 2 cores, 2 threads				
Intel® HD Graphics 510				
Supports DDR4 memory up to 2133 MT/s data rate				
Intel® 6th Generation Celeron® Processors	400 G3 DM	400 G4 SFF		480 G4 MT
Intel® Celeron ® G3900 Processor		X	X	X
51W				
2.8 GHz Base Frequency				
2 MB cache, 2 cores, 2 threads				
Intel® HD Graphics 510				

Overview

Intel® Celeron ® G3900T Processor
35W
2.6 GHz Base Frequency
2 MB cache, 2 cores, 2 threads
Intel® HD Graphics 510
Supports DDR4 memory up to 2133 MT/s data rate

X

Standard Features and Configurable Components

MEMORY*

Form Factor	Туре	Maximum	Number of Slots
400 G3 DM	DDR4-2400 (Transfer rates up to 2400 MT/s)	32 GB	2 SODIMM
400 G4 SFF	DDR4-2400 (Transfer rates up to 2400 MT/s)	32 GB	2 DIMM
400 G4 MT	DDR4-2400 (Transfer rates up to 2400 MT/s)	32 GB	2 DIMM
480 G4 MT	DDR4-2400 (Transfer rates up to 2400 MT/s)	32 GB	2 DIMM

Both slots are customer accessible / upgradeable.

- 2,048 MB (2048 MB x 1)
- 4,096 MB (4096 MB x 1)
- 8,192 MB (8192 MB x 1)
- 16,384 MB (16,384 MB x 1)

STORAGE*

2.5 inch 7.2k RPM Hard Disk Drives	400 G3 DM	400 G4 SFF	400 G4 MT	480 G4 MT
1TB SATA	X	X	X	X
500GB SATA	X	X	X	X
3.5" SATA 7.2k RPM Hard Disk Drives	400 G3 DM	400 G4 SFF	400 G4 MT	480 G4 MT
500GB 7200RPM 3.5in		X	X	X
1TB 7200RPM 3.5in		×	×	X
2TB 7200RPM 3.5in		X	X	X
2.5 inch Solid State Hybrid Drives				
(SSHD)	400 G3 DM	400 G4 SFF	400 G4 MT	480 G4 MT
1TB 5400RPM 2.5in 8GB Hybrid	×	X	X	X
500GB 5400RPM 2.5in 8GB Hybrid	X	X	X	X
3.5 inch Solid State Hybrid Drives (SSHD)	400 G3 DM	400 G4 SFF	400 G4 MT	480 G4 MT
1TB 7200RPM 3.5in SSHD (SSHD)		x	X	x
2.5 inch Self-encrypting Drives (SED HDD)	400 G3 DM	400 G4 SFF	400 G4 MT	480 G4 MT
500GB 7200RPM 2.5in SED 0PAL2	X	X	X	X

^{*} Full availability of 4 GB or more of memory requires a 64-bit operating system. With Windows 32-bit operating systems, the amount of usable memory is dependent upon your configuration, so that above 3 GB all memory may not be available due to system resource requirements. Memory modules support data transfer rates up to 2400 MT/s; actual data rate is determined by the system's configured processor. See processor specifications for supported memory data rate.

Standard Features and Configurable Components

2.5 inch Self-encrypting Drives (SED
-----------------------------------	-----

SSD)	400 G3 DM	400 G4 SFF	400 G4 MT	480 G4 MT
256GB TLC SED SSD Opal 2 Drive	X	Χ	X	X
512GB TLC SED SSD Opal 2 Drive	X	X	X	X
PCIe NMVe SSD Drives	400 G3 DM	400 G4 SFF	400 G4 MT	480 G4 MT
HP 256GB Turbo Drive G2 PCIe TLC SSD Drive	X	X	x	X
HP 512GB Turbo Drive G2 PCIe TLC SSD Drive	X	X	X	Х
HP 1TB Turbo Drive G2 PCIe TLC SSD Drive	X	×	×	Х

2.5 SATA SSD Drives	400 G3 DM	400 G4 SFF	400 G4 MT	480 G4 MT
HP SATA 128GB SSD Drive	x	X	X	Х
HP SATA 256GB SSD Drive	x	X	X	Х
HP 256GB TLC SSD Drive	x	X	Х	Х
HP 512GB TLC SSD Drive	X	×	×	Х

^{*}For storage drives, GB = 1 billion bytes, TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30GB of system disk is reserved for system recovery software.

Optical Disc Drives	400 G3 DM	400 G4 SFF	400 G4 MT	480 G4 MT
HP 9.5mm G3 800/600/400 SFF G4 400 Microtower DVD-Writer*		X	X	X
HP 9.5mm G3 800/600/400 SFF G4		×	X	X

^{*}HD-DVD discs cannot be played on this drive. No support for DVD-RAM. Actual speeds may vary. Don't copy copyright-protected materials. Double Layer discs can store more data than single layer discs. Discs burned with this drive may not be compatible with many existing single-layer DVD drives and players.

Media Card Reader	400 G3 DM	400 G4 SFF	400 G4 MT	480 G4 MT
(Optional)* SD3 with 5-in-1		X	X	X
Interface from SD option to PCA is USB (Supports SD, SDXC, SDHC, UHS-I,				
UHS-II)				

*Card sold separately

GRAPHICS

Standard Features and Configurable Components

System Integrated Graphics	400 G3 DM	400 G4 SFF	400 G4 MT	480 G4 MT
Intel® HD Graphics 530 (integrated on 6 th gen Core i7/i5/i3 processors)	Х	X	x	Х
Intel® HD Graphics 630 (integrated on 7 th gen Core i7/i5/i3 processors and Pentium G4620, 4600, 4600T)	Х	X	X	Х
Intel® HD Graphics 610 (integrated on Pentium G4560, G4560T, Celeron G3950, G3930, G3930T)	x	×	×	X

Optional Discrete Graphics Solutions

(optional and RX 460 device must be configured at purchase)	400 G3 DM	400 G4 SFF	400 G4 MT	480 G4 MT
AMD Radeon? R7 450 4GB FH PCIe x16*			X	X
AMD Radeon? RX 460 2GB FH PCIe x16*			X	X
NVIDIA® GeForce® GT730 1GB PCIe x8 HDMI		X	X	X
NVIDIA® GeForce® GT730 2GB PCIe x8 DP		X	X	Х
*Requires 310W chassis				
2 nd Graphics Cards	400 G3 DM	400 G4 SFF	400 G4 MT	480 G4 MT
AMD Radeon? R7 450 4GB FH PCIe x16 G5 2nd**			Х	X
NVIDIA® GeForce® GT730 1GB PCIe x8 HDMI 2nd***		X	X	Х
NVIDIA® GeForce® GT730 2GB PCIe x8 DP 2nd****		×	×	×

^{**}Available only with AMD Radeon? R7 450.

AUDIO/MULTIMEDIA

	400 G3 DM	400 G4 SFF	400 G4 MT	480 G4 MT	
Conexant CX20632 Audio Codec	х	X	Х	X	
Headset* front connector (3.5mm)	X	X	X	X	
Headphone front connector (3.5mm)	X				
Line-out and Line-In rear connectors* (3.5mm)		X	X	X	
Multi-streaming capable**	X	X	X	X	
Internal speaker (standard)	X	×	×	×	

^{*}The DM, SFF, MT front headset connector supports CTIA style headsets. Headset connectors are retaskable to function as a Line-In, Microphone-In, Line-out or Headphone-out port. Rear audio input ports are re-taskable as a Line-in or Microphone-in port. External speakers must be powered externally.

NETWORKING/COMMUNICATIONS*

^{***}Available only with NVIDIA® GeForce® GT730 1GB.

^{****}Available only with NVIDIA® GeForce® GT730 2GB

^{**}Multi-streaming can be enabled in the audio control panel to allow independent audio streams to be sent to/from the separate connectors or internal speakers. This allows for different audio applications to use separate audio ports on the system. For example, the front connector could be used with a headset for a communications application while the rear connector is being used with external speakers and a multimedia application.



Standard Features and Configurable Components

Ethernet (RJ-45) Integrated	400 G3 DM	400 G4 SFF	400 G4 MT	480 G4 MT
Realtek RTL8111 HSH GbE LOM Network Connection (standard)	X	X	X	X
Ethernet (RJ-45) Optional	400 G3 DM	400 G4 SFF	400 G4 MT	480 G4 MT
Intel® Ethernet I210-T1 PCIe x1 Gb Network Interface Card (optional)		Х	Х	X
Wireless LAN (optional and all except for 7265 for SFF/TWR must be bought at purchase)	400 G3 DM	400 G4 SFF	400 G4 MT	480 G4 MT
Intel® 7265 802.11AC 2x2 Wi-Fi +Bluetooth M.2 Combo Card non-VPro	×	X	X	X
Intel® 3168 802.11AC 1x1 Wi-Fi +Bluetooth M.2 Combo Card non-VPro	X	X	X	X
Intel® 7260 802.11 a,b,g,n 2x2 M.2 Bluetooth® Disabled NIC**	X			

^{*} Wireless access point and Internet service required and not included. Availability of public wireless access points limited.

SLOTS

	400 G3 DM	400 G4 SFF	400 G4 MT	480 G4 MT
Turbo Drive (M.2 PCle)	1 ea. M.2 PCIe x1- 2230 (for WLAN)	1 ea. M.2 PCIe x1- 2230 (for WLAN)	1 ea. M.2 PCIe x1- 2230 (for WLAN)	1 ea. M.2 PCIe x1- 2230 (for WLAN)
	1 ea. M.2 PCle x4- 2280/2230 (for storage)			
PCI Express x1 (v3.0)	N/A	N/A	1 ea. 4.2"? full height 6.6"? length 10W max. power	N/A
PCI Express x16 (v3.0) (wired as a x4)	N/A	1 ea. 2.5"? low profile 6.6"? length 35W max. power	1 ea. 4.2"? full height 6.6"? length 35W max. power	1 ea. 4.2"? full height 6.6"? length 35W max. power
PCI Express x16 (v3.0)	N/A	1 ea. 2.5"? low profile 6.6"? length 35W max. power	1 ea. 4.2"? full height 6.6"? length 75W max. power	1 ea. 4.2"? full height 6.6"? length 75W max. power
PCI	N/A	N/A	N/A	1 ea. 4.2"? full height 6.6"? length

PORTS

^{**}Wake on Lan feature is not available.

Standard Features and Configurable Components

I/O Ports -Standard

	400 G3 DM	400 G4 SFF	400 G4 MT	480 G4 MT
USB 2.0	2 (rear)	4 (rear)	4 (rear)	4 (rear)
USB 3.1 Gen1	2 (front) including 1 fast charging 2 (rear)	2 (front); 2 (rear)	2 (front); 2 (rear)	2 (front); 2 (rear)
USB Type-C?3.0 port	N/A	N/A	N/A	N/A
PS/2	N/A	Optional (see I/O Ports Optional below)	Optional (see I/O Ports Optional below)	Optional (see I/O Ports Optional below)
Video	1* DisplayPort? 1* port (choice of DisplayPort?, HDMI or VGA)	1DisplayPort? ; 1 VGA	1 DisplayPort? 1 VGA	1 DisplayPort?; 1 VGA
Audio	Front: 1 Headset 1 Headphone	Front: 1 Headset; Rear: 1 Audio-out 1 Audio-in	Front: 1Headset; Rear: 1 Audio-out 1 Audio-in	Front: 1 Headset; Rear: 1 Audio-out 1 Audio-in
Network Interface	RJ-45	RJ-45	RJ-45	RJ-45

L	0/	Ports	: _

Optional	400 G3 DM	400 G4 SFF	400 G4 MT	480 G4 MT
Serial (RS-232)	1 standard; 1 optional*	N/A	1 (optional) (rear)	1 (optional) (rear)
Serial (RS-232) and PS/2 combination	N/A	1 (optional)	1 (optional)	1 (optional)

^{*}Replaces 1 of the optional video ports

I/O Ports —

.,				
Internal ports	400 G3 DM	400 G4 SFF	400 G4 MT	480 G4 MT
DM SATA storage connector	1	N/A	N/A	N/A
Internal SATA storage connector(s)	N/A	2	3	3

Standard Features and Configurable Components

BAYS

	400 G3 DM	400 G4 SFF	400 G4 MT	480 G4 MT
5.25" Half Height ODD	N/A	N/A	N/A	N/A
9mm Slim ODD	N/A	1 ea.	1 ea.	1 ea.
Secure Digital (SD) 3 Reader	N/A	1 ea.	1 ea.	1 ea.
2.5"? internal storage drive	1 ea.	1 ea.*	1 ea.*	1 ea.*
3.5"? internal storage drive	N/A	1 ea.*	2 ea.*	2 ea.*

^{*}SFF can be configured with either (1) 3.5"? or (1) 2.5"? internal storage drive; MT can be configured with either (2) 3.5"? or (1) 3.5"? and (1) 2.5"? internal storage drive.

KEYBOARDS AND POINTING DEVICES

Keyboards	400 G3 DM	400 G4 SFF	400 G4 MT	480 G4 MT
HP Conferencing Keyboard	х	Х	Х	Х
HP USB PS/2 Washable Keyboard*	x	X	X	X
HP USB Business Slim CCID SmartCard Keyboard	x	X	x	X
HP USB Business Slim Keyboard	x	X	x	X
HP PS/2 Business Slim Keyboard		X	x	X
HP USB Business Slim Keyboard (China only)	x	x	x	x
HP USB Business Slim Grey Keyboard	X	x	x	X

Mice	400 G3 DM	400 G4 SFF	400 G4 MT	480 G4 MT
HP PS/2 Mouse*		Х	Х	Х
HP USB 1000dpi Laser Mouse	X	X	X	X
HP Grey V2 Mouse	X	X	x	X
HP USB Mouse	X	X	x	X
HP USB PS/2 Washable Mouse*	X	X	x	X
HP USB Mouse (China only)	x	x	x	X
HP USB Hardened Mouse	X	x	x	X

Combo	400 G3 DM	400 G4 SFF	400 G4 MT	480 G4 MT
HP Wireless Business Slim Keyboard and Mouse*	х	Х	Х	х
HP USB Keyboard and Mouse (China only)	x	x	X	X

Other	400 C2 DM 400 C4 CFF 400 C4 MT 400 C4 MT
Other	400 G3 DM 400 G4 SFF 400 G4 MT 480 G4 MT
HP Mouse Pad	x x x x

^{*}Note Optional HP Internal Serial/PS/2 Ports is required to support this device.

ADAPTERS AND CABLES

Standard Features and Configurable Components

	400 G3 DM	400 G4 SFF	400 G4 MT	480 G4 MT
HP DisplayPort? Cable	Х	Х	Х	Х
HP DisplayPort? to DVI-D Adapter	x	X	X	x
HP DisplayPort? to HDMI 4K Adapter	x	X	X	x
HP DisplayPort? to VGA Adapter	x	X	X	x
HP DVI Cable	x	X	x	x
HP 700mm DisplayPort? Cable Kit	x			
HP USB to Serial Port Adapter	x			

DUST FILTERS

	<u>DM</u>	SFF	<u>MT</u>
G3 600 SFF/ G4 SFF Dust Filter		X	
HP G3 Mini Dust Filter	x		
G4 400 MT Dust Filter			Х

Desktop Mini Accessories (optional)

	<u>DM</u>	<u>SFF</u>	<u>MT</u>
HP Desktop Mini DVD-Writer ODD Expansion Module	X		
HP Desktop Mini 500GB HDD/ I/O Expansion Module	×		
HP Desktop Mini I/O Expansion Module	×		
HP Desktop Mini Security/Dual VESA Sleeve	×		
HP DM VESA Power Supply Holder	Х		
HP DM VESA Quick Deploy Adhesive	Х		
HP Desktop Mini Vertical Chassis Stand	Х		
HP Desktop Mini Port Cover Kit	Х		
HP Quick Release Bracket	Х		
HP DM Antenna/Wiring WLAN Kit	Х		
HP PC Mounting Bracket for Monitors	X		

SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS

BIOS

HP BIOSphere Gen3¹

HP DriveLock | HP Automatic DriveLock

BIOS Update via Network

Master Boot Record Security

Power On Authentication

Secure Erase²

Absolute Persistence Module³

Pre-boot Authentication

HP LAN-WLAN Protection

HP Wireless Wakeup

Multi Media

CyberLink Power Media Player (select models only)

Standard Features and Configurable Components

CyberLink Power2Go (select models only)

Communication / Connectivity

Native Miracast Support⁴

HP Value Add Software

HP ePrint Driver + JetAdvantage⁵

HP Hotkey Support - CMIT

HP Recovery Manager

HP Recovery Disc Creator (Windows 7 only)

HP Jumpstart

HP Support Assistant

HP Noise Cancellation Software

HP Velocity

HP Notifications

3rd Party

Foxit PhantomPDF Express for HP (Windows 7 only)

Microsoft Products

Buy Office

Bing Search

Skype⁶

Manageability

HP Driver Packs⁷

HP SoftPaq Download Manager (SDM)

HP System Software Manager (SSM)⁷

HP BIOS Config Utility (BCU)8

HP Client Catalog⁷

HP Manageability & Integration Kit (MIK)⁷

LANDESK Management⁸

For more information on HP Client Management Solutions refer to: http://www.hp.com/go/clientmanagement

Client Security Software

HP Client Security

- HP Security Manager (including Credential Manager and Password Manager)
- HP Drive Lock
- HP Password Manager
- Absolute Persistence Module
- Power On Authentication

Microsoft Security Essentials⁹ (Windows 7 only) Microsoft Defender HP WorkWise (requires Bluetooth)¹⁰

Standard

Trusted Platform Module (TPM) 2.0 (Infineon SLB9670). Common Criteria EAL4+ Certified.

Downgradeable to TPM 1.2. Convertible to FIPS 140-2 Certified mode. (TPM 2.0 is not available for Win 7 32-bit.) Restrictions apply; contact your account manager for more details.

Standard Features and Configurable Components

For more information on HP Client Security Software Suite, refer to http://www.hp.com/go/clientsecurity.

- 1 HP BIOSphere Gen 3 requires Intel® or AMD 7th generation processors.
- 2 For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88.
- 3 Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit: http://www.absolute.com/company/legal/agreements/ computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.
- 4 Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming media players that also support Miracast. You can use Miracast to share what you're doing on your PC and present a slide show. For more information: http://windows.microsoft.com/en-us/windows-8/project-wireless-screen-miracast
- 5 Requires an Internet connection to HP web-enabled printer and HP ePrint account registration (for a list of eligible printers, supported documents and image types and other HP ePrint details, see www.hp.com/go/eprintcenter). Requires optional broadband module. Broadband use requires separately purchased service contract. Check with service provider for coverage and availability in your area. Separately purchased data plans or usage fees may apply. Print times and connection speeds may vary.
- 6 Skype is not offered in China.
- 7 Not preinstalled, however available for download at http://www.hp.com/go/clientmanagement
- 8 Subscription required.
- 9 Opt in and internet connection required for updates.
- 10 HP WorkWise smartphone app will soon be available as a free download on the App Store and Google Play. Requires Windows 10 Build 1607 or higher).

HP BIOS

Key features of the HP BIOS include:

- Deployment and manageability HP BIOS provides several technologies that help integrate the HP Pro 400 G3/G4
 Business PC into the enterprise, such as PXE, remote configuration, remote control, and F10 Setup support for 14
 languages.
- Update your BIOS via the cloud or standardize on a BIOS version hosted on Enterprise network.
- Stability HP BIOS supports the HP stable product roadmap by releasing only critical BIOS changes to the factory and advanced change notification.
- UEFI specification 2.5
- Absolute Persistence agent For tracking and tracing services, available in select countries, separate software and purchase of a subscription is required.
- Thermal and power management The HP BIOS provides and enables thermal and power management technologies so
 component temperatures are managed for high reliability and to assist in operating the HP Business Desktop computer
 in any enterprise environment.
- Acoustic performance Industry leading acoustic emissions across the range of operating conditions.
- Serviceability HP BIOS provides diagnostic and detailed service information.
- Upgrades and recovery HP BIOS provides numerous ways to upgrade HP Business Desktop computers, including BIOS updates from within Windows (HPBIOSUPDREC), HP Client Manager, and fail-safe recovery. In addition, the HP BIOS Configuration Utility enables replication of BIOS settings within Windows while the Replicated Setup feature provides the same capability within F10 setup. The BIOS Configuration Utility is available from the support website.
- HP BIOS uses PKI signing of the BIOS for trusted BIOS upgrades and recovery.

Additional HP BIOS Features:

- Power-On password Helps prevent an unauthorized user from powering on the system.
- Administrator password Also known as the setup password, this helps prevent unauthorized changes to the system configuration. If the administrator password is not known, the BIOS version cannot be changed and changes cannot be made to BIOS settings using F10 setup or under the OS.
- Advanced Configuration and Power Interface (ACPI) Represents a significant innovation in power and configuration
 management, allowing operating systems and applications to manage power based on activity and usage. HP Pro
 models use ACPI to provide power conservation features.

S5 Max Power Savings setting supports EU Lot6 requirement and allows the computer to power down below 0.5W in S5 (when turned off). When S5 Max Power Savings feature is enabled below features are turned off:

Standard Features and Configurable Components

- Power to slots
- Wake events other than power buttons (such as Wake on LAN)
- USB charging ports

HARDWARE SECURITY

SATA 0,1 port disablement (via BIOS)

Serial, USB enable/disable (via BIOS)

Hood Sensor for DM (integrated in the PCA, can be enabled/disabled through BIOS)

Support for chassis padlocks and cable lock devices

POWER SUPPLY

	400 G3 DM	400 G4 SFF	400 G4 MT	480 G4 MT
Standard Efficiency	65W 89% average efficiency at 115Vac & 230Vac			
80 PLUS Bronze	N/A	180W active PFC 82/85/82% efficient at 20/50/100% load(115V)	180W active PFC 82/85/82% efficient at 20/50/100% load(115V) 310W active PFC 82/85/82% efficient at 20/50/100% load(115V)	180W active PFC 82/85/82% efficient at 20/50/100% load(115V) 310W active PFC 82/85/82% efficient at 20/50/100% load(115V)
Operating Voltage Range	90 - 264VAC	90 - 264VAC	90 - 264VAC	90 - 264VAC
Rated Voltage Range	100 - 240VAC	100 - 240VAC	100 - 240VAC	100 - 240VAC
Rated Line Frequency	50 - 60HZ	50 - 60HZ	50 - 60HZ	50 - 60HZ
Operating Line Frequency	47 - 63HZ	47 - 63HZ	47 - 63HZ	47 - 63HZ
Rated Input Current	65W/1.6A90W/1.4A	180W/2.3A	180W/2.3A 310W/4A	180W/2.3A 310W/4A
Rated Input Current with Energy Efficient* Power Supply	90W/1.4A	180W/2.3A	180W/2.3A 310W/4A	180W/2.3A 310W/4A

Standard Features and Configurable Components

DC Output	+19.5V	+12V	+12V	+12V
Current Leakage (NFPA 99: 2102)	Less than 500 micro amps of leakage current at 120 Vac with the ground wire disconnected, as required for Nonpatient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1.	Less than 500 micro amps of leakage current at 120 Vac with the ground wire disconnected, as required for Nonpatient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1.	Less than 500 micro amps of leakage current at 120 Vac with the ground wire disconnected, as required for Nonpatient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1.	Less than 500 micro amps of leakage current at 120 Vac with the ground wire disconnected, as required for Nonpatient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1.
	Less than 100 micro amps of leakage current at 120 Vac with the ground wire intact with normal polarity, as required for Nonpatient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1.	Less than 100 micro amps of leakage current at 120 Vac with the ground wire intact with normal polarity, as required for Nonpatient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1.	Less than 100 micro amps of leakage current at 120 Vac with the ground wire intact with normal polarity, as required for Nonpatient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1.	Less than 100 micro amps of leakage current at 120 Vac with the ground wire intact with normal polarity, as required for Nonpatient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1.
Power Supply Fan	N/A	70mm variable speed	70mm variable speed	70mm variable speed
Power cord length	6.0 ft. (1.83 m) (Power cord only)	6.0 ft. (1.83 m)	6.0 ft. (1.83 m)	6.0 ft. (1.83 m)
External Powe	r Adapter			
Dimensions	55x30x114mm (60W)	N/A	N/A	N/A
Total Cord Length	6 ft	N/A	N/A	N/A

^{*}High efficiency power supply is a requirement for ENERGY STAR® certification in conjunction with a select range of processors and modules

WEIGHTS & DIMENSIONS

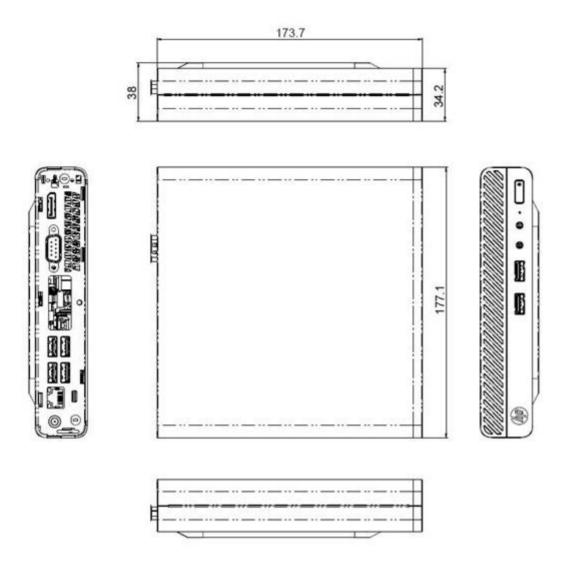
(Configured with 2TB HDD, Wi-Fi card, graphics card)

Standard Features and Configurable Components

	400 G3 DM	400 G4 SFF	400 G4 MT	480 G4 MT
Chassis (W x D x H)	6.97 x 6.88 x 1.35 in	10.6 x 11.7 x 3.7 in	6.69 x 10.79 x 13.3 in	6.69 x 10.79 x 13.3 in
not including bezel	177 x 174.7 x 34.2 mm	270 x 296 x 95 mm	170 x 274 x 338 mm	170 x 274 x 338 mm
System Volume	64 cu in	463 cu in	960 cu in	960 cu in
	1.06 L	7.6 L	15.74 L	15.74 L
System Weight*	2.67 lb	10.14 lb	12.06 lb	12.06 lb
	1.21 kg	4.6 kg	5.47 kg	5.47 kg
Max Supported	N/A	77 lb	77 lb	77 lb
Weight (desktop orientation)		35 kg	35 kg	35 kg
Packaging (W x D x	9.1 x 19.6 x 5.7 in	15.71 x 9.06 x 19.65 in	15.35 x 11.73 x 19.65 x in	15.35 x 11.73 x 19.65 x in
H)	497.8 x 144.8 x 231.1 mm	399 x 230 x 499 mm	390 x 298 x 499 mm	390 x 298 x 499 mm
Shipping Weight	6.1 lb	15.59 lb.	20.26 lb.	20.26 lb.
	2.8 kg	7.08 kg	9.2 kg	9.2 kg
Palletization Profile	20-units per layer	6-units per layer	6-units per layer	6-units per layer
	4 layer max 80-units per pallet	10 layer max 60 per pallet	7 layer max 42 per pallet	7 layer max 42 per pallet
	Footprint-39.21 x 46.61 in	47.24 x 39.37 x 94.49 in	47.24 x 39.37 x 86.85 in	47.24 x 39.37 x 86.85 in
	(996 x 1184 mm)	(including pallet)	(including pallet)	(including pallet)
	Dependent on 40-Ft Stnd.			
	Sea Container or 40-Ft			
	High-cube Sea Container is			
	used)			

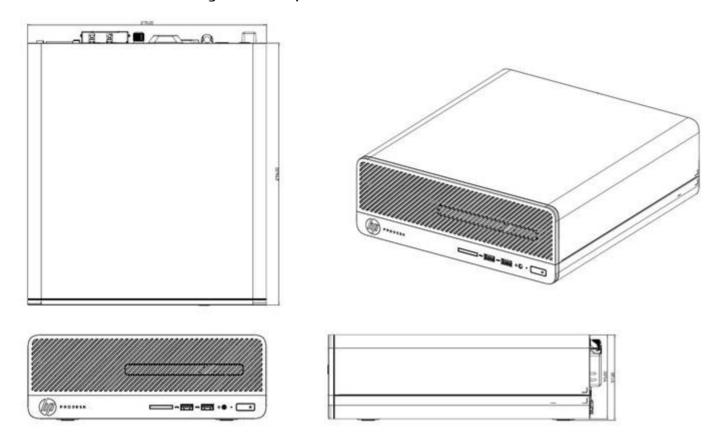
Desktop Mini Dimensions

Standard Features and Configurable Components

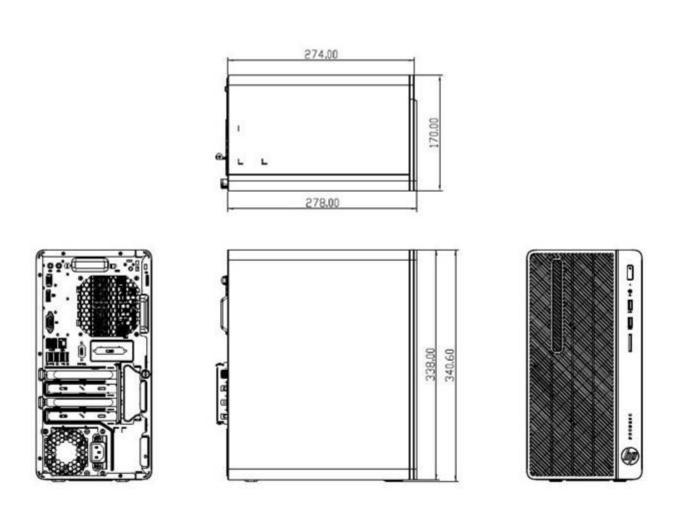


Small Form Factor Dimensions

Standard Features and Configurable Components



Mictrotower Dimensions





Technical Specifications – Environmental

ENVIRONMENTAL & INDUSTRY

Eco-Label Certifications & declarations

This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- IT ECO declaration
- US ENERGY STAR®
- EPEAT <Gold> registered in the United States. See http://www.epeat.net for registration status in your country.

System Configuration

The configuration used for the Energy Consumption and Declared Noise Emissions data for the Desktop model is based on a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.

Energy
Consumption
(in accordance
with US
ENEDGY STAD

ENERGY STAR®			
test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal	14.26 W	14.19 W	14.22 W
Operation			
(Short idle)			
Normal	13.31 W	13.03 W	13.28 W
Operation			
(Long idle)			
Sleep	0.75 W	0.83 W	0.75 W
Off	0.63 W	0.71 W	0.63 W

Note:

Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family . HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.

Heat	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Dissipation*			
Normal	49 BTU/hr	49 BTU/hr	49 BTU/hr
Operation			
(Short idle)			
Normal	46 BTU/hr	45 BTU/hr	45 BTU/hr
Operation			
(Long idle)			
Sleep	3 BTU/hr	3 BTU/hr	3 BTU/hr
Off	2 BTU/hr	2 BTU/hr	2 BTU/hr

*NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Declared Noise	Sound Power	Sound Pressure
Emissions	(L _{WAd} , bels)	(L _{pAm} , decibels)
(in accordance		
with		



Technical Specifications – Environmental

ISO 7779 and		
ISO 9296)		
Typically	3.6	26
Configured -		
Idle		
Fixed Disk -	3.7	26
Random writes		

Batteries

This battery(s) in this product comply with EU Directive 2006/66/EC

Batteries used in the product do not contain:

Mercury greater the1ppm by weight

Cadmium greater than 20ppm by weight

Battery size: CR2032 (coin cell)

Battery type: Lithium

Additional Information

- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- This product is in compliance with the IEEE 1680 (EPEAT) standard at the <gold> level, see www.epeat.net
- Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.
- This product contains 20.3% post-consumer recycled plastic (by wt.)
- This product is 92.7% recycle-able when properly disposed of at end of life.

Packaging Materials	External:	PAPER/Paper	990 g			
	•	PAPER/Paperboard	210 g			
	Internal:	PLASTIC/Polyethylene Expanded - EPE	121 g			
		PLASTIC/Polyethylene high density - HDPE	19 g			
	The Plastic packaging material is made from 80% recycled content.					
	The paper package	ging materials contains at least 80% recycled cont	ent.			
Material	This product does not contain any of the following substances in excess of regulatory					
Usage	limits (refer to the I	HP General Specification for the Environment at				
	http://www.hp.con	n/hpinfo/globalcitizenship/environment/pdf/gse.pdf):			

- Asbestos
 - Certain Azo Colorants
 - Certain Brominated Flame Retardants may not be used as flame retardants in plastics
 - Cadmium
 - Chlorinated Hydrocarbons
 - Chlorinated Paraffins
 - Formaldehyde
 - Halogenated Diphenyl Methanes



Technical Specifications - Environmental

- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Packaging Usage

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and Recycling

Hewlett-Packard offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

HP, Inc. Corporate Environmental Information

For more information about HP's commitment to the environment:

Global Citizenship Report

http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html

Eco-label certifications

http://www8.hp.com/us/en/hp-information/environment/ecolabels.html

ISO 14001 certificates:

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_ Design_ISO_14K_Certificate.pdf

and

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf



Technical Specifications – Environmental

ENERGY STAR® certified models available

EPEAT® registered where applicable/supported. See http://www.epeat.net for registration status by country.

TAA compliant models available

UNIT ENVIRONMENT AND OPERATING CONDITIONS

General Unit Operating Guidelines

- Keep the computer away from excessive moisture, direct moisture and the extremes of heat and cold, to ensure that unit is operated within the specified operating range.
- Leave a 10.2 cm (4 in) clearance on all vented sides of the computer to permit the required airflow.
- Never restrict airflow into the computer by blocking any vents or air intakes.
- Do not stack computers on top of each other or place computers so near each other that they are subject to each other's re-circulated or preheated air.
- Occasionally clean the air vents on the front, back, and any other vented side of the computer. Lint, dust and other foreign matter can block the vents and limit the airflow.
- If the computer is to be operated within a separate enclosure, intake and exhaust ventilation must be provided on the enclosure, and the same operating guidelines listed above will still apply.

Temperature Range Operating: 50° to 95° F (10° to 35° C)*

Non-operating: -22° to 140° F(-30° to 60° C)

Relative Humidity Operating: 10% to 90% (non-condensing at ambient)

Non-operating: 5% to 95% (non-condensing at ambient)

Maximum Altitude Operating: 5000m

(unpressurized) Non-operating: 50000ft (15240 m)

*Operating temperature is de-rated 1.0 deg C per 300 m (1000 ft) to 3000 m (10,000 ft) above sea level, no direct sustained sunlight. Maximum rate of change is 10 deg C/Hr. The upper limit may be limited by the type and number of options installed.

SERVICE AND SUPPORT

On-site Warranty ¹: Three-year (3-3-3) limited warranty delivers three years of on-site, next business day ² service for parts and labor and complimentary limited technical support. ³ Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Pack. ⁴ To choose the right level of service for your HP product, visit HP Care Pack Central: www.hp.com/go/cpc

NOTE 1: Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.

NOTE 2: On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

NOTE 3: Technical telephone support applies only to HP-configured and third-party HP qualified hardware and software.

NOTE 4: Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

Technical Specifications – Environmental



Technical Specifications – Graphics

GRAPHICS

Intel® HD Graphics (integrated)

DisplayPort? Multimode capable; supports HDCP, DisplayPort? Audio (2 streams), HBR2 link rates

and Multi-Stream Technology for a maximum of 2 displays.

Memory The BIOS has options for selecting the dedicated memory size of 128MB, 256MB or

512MB

Additional memory is allocated for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an optimal balance between graphics and

system memory use.

Maximum Graphics Memory Windows 10

>4 GB

Note: the actual amount of maximum graphics memory can be less than the amounts

listed above depending upon your computer's configuration.

Maximum Color Depth 32 bits/pixel

Graphics/Video API Support

6th Generation Intel Core Processors7th Generation Intel Core ProcessorsWith Intel Graphics 580, 550, 540With Intel HD Graphics 620, 615

With Intel HD Graphics 530, 520, 515

DirectX OpenGL OpenCL Intel DirectX OpenGL OpenCL Intel Quick Quick Sync Sync Video Video 12 4.4 2.0 Yes 12 4.4 2.0 Yes

7th Generation Intel Core Processors

With Intel HD Graphics 505, 500

DirectX OpenGL OpenCL Intel
Quick
Sync
Video

12 4.2 1.2 Yes

Media Playback <u>6th Generation Intel Core Processors</u> <u>7th Generation Intel Core Processors</u>

Premium Content & Content 4K UHD 4K UHD, BD UHD, UHD-HDR

protection

HW Codec HEVC 8b, VP8 HEVC 10b, VP9 10b Decode,

8b Encode

Visual Quality Highest HQV Highest HQV, BT2020 for HDR playback



Technical Specifications – Graphics

Supported Display Resolutions and Refresh Rates

Note: other resolutions may be available but are not recommended as they may not have been tested and qualified by HP. For All in One platforms, resolutions higher than the integrated panel resolution are not supported on the integrated panel.

DisplayPort

Resolution	Refresh Rate	VGA	risplayeoi t ?	HDMI	Standard
640 x 480	60, 75, 85	Х	X	- ×	VESA DMT, CVT 0.31M3
720 × 400	70	Х	X	- ×	IBM VGA
800 × 600	60, 75, 85	Х	X	- ×	VESA DMT, CVT0.48M3
1024 × 768	60, 75, 85	X	X	- ×	VESA DMT, CVT 0.79M3
1152 x 864	60, 75, 85	Х	X	- ×	VESA DMT, CVT 0.83MA
1280 x 720	60, 75, 85	Х	X	- ×	VESA DMT, CVT 0.92M9, CEA-770.3
1280 x 768	60, 60RB, 75, 85	Х	X	- ×	VESA DMT, CVT 0.98M9/0.98M9-R
1280 x 800	60, 75, 85	X	X	- ×	VESA DMT
1280 x 960	60, 75, 85	X	X	- ×	VESA DMT
1280 x 1024	60, 75, 85	X	X	- ×	VESA DMT, CVT 1.31M4
1366 x 768	60, 60RB	X	X	- ×	VESA DMT
1440 × 900	60, 60RB	X	X	- ×	VESA DMT
1600 × 900	60, 60RB, 75, 85	X	X	- ×	VESA DMT
1680 x 1050	60, 60RB, 75	X	X	- ×	VESA DMT, CVT 1.76MA/1.76MA-R
1920 x 1080	60	X	X	- ×	VESA DMT, CVT 2.07M9, SMPTE 274M
1920 x 1200	60, 60RB, 75, 85	X*	X	- ×	DMT, CVT 2.30MA/2.30MA-R
1600 x 1200	60, 75, 85	X*	X	- ×	VESA DMT, 1.92M3
1920 x 1440	60, 75, 85		X	- ×	VESA DMT, CVT 2.76M3
2048 x 1536	60,75		X	- ×	CVT 3.15M3
2560 x 1440	59.951		X	- ×	CVT 3.69M9-R
2560 x 1600	60, 60RB		X	- ×	VESA DMT, CVT 4.10MA/4.10MA-R
3840 x 2160	24		X	- ×	CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
3840 x 2160	25		X	- ×	CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
3840 x 2160	30		X	- ×	CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
3840 x 2160	50		X	- ×	CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
3840 x 2160	60		X	- ×	CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
4096 x 2160	24		X	- ×	CVT-RBv1/v2 (8.85M-R), SMPTE 274M
4096 x 2160	25		X	- ×	CVT-RBv1/v2 (8.85M-R), SMPTE 274M
4096 x 2160	30		X	- x	CVT-RBv1/v2 (8.85M-R), SMPTE 274M
4096 x 2160	50		X	- x	CVT-RBv1/v2 (8.85M-R), SMPTE 274M
4096 x 2160	60		X	- ×	CVT-RBv1/v2 (8.85M-R), SMPTE 274M
				_	

Technical Specifications – G	iraphics			
1920 x 1080	60	X	X	VESA (SMPTE 274M)
1920 x 1080	50	×	×	SMPTE 274M
1920 x 1080	30	×	X	SMPTE 274M
1920 x 1080	24	x	X	SMPTE 274M
1280 x 720	60	x	X	VESA (CEA-770.3)
1280 x 720	50	x	X	SMPTE 296M
720 x 480	60	×	×	MHL (CEA-770.2)
720 x 576	50	×	×	ITU-R BT.1358
640 x 480	60	×	X	CEA (VESA DMT)
		_		

^{* 60}Hz refresh rate only on VGA

AMD Radeon? R7 450 4GB PCIe x16 Graphics Card

Memory 4GB 128-bit wide frame buffer operating at 1125MHz.

Controller Clock Speed AMD® Radeon? R9 450 GPU operating at 925 MHz

Multi-display Support A maximum of 4 displays are supported by the card. A maximum of 2 legacy displays (Native VGA,

DVI, or displays connected with passive DisplayPort? adapters are considered as legacy)

Graphics /API support DIRECTX 12, Open GL 4.3, Open CL1.2, UVD 3

Output Connectors 1 x Dual-Link DVI-I, 1x DisplayPort?; 1x HDMI; Includes DVI to VGA adapter

VGA

Supported Display Resolutions and Refresh Rates

Note: other resolutions may be available but are not recommended as they may not have been tested and qualified by HP

		(DVI- VGA adapter)	DVI- D	DisplayPort ?		HDMI
Resolution	Refresh Rate*					Standard
640 x 480	60, 75, 85	X	Х	Х	Х	VESA DMT, CVT 0.31M3
720 x 400	70	х	X	Х	Х	IBM VGA
800 x 600	60, 75, 85	х	X	Х	Х	VESA DMT, CVT0.48M3
1024 x 768	60, 75, 85	х	X	Х	Х	VESA DMT, CVT 0.79M3
1152 x 864	60, 75, 85	х	X	Х	Х	VESA DMT, CVT 0.83MA
1280 x 720	60, 75, 85	X	X	Х	Х	VESA DMT, CVT 0.92M9, CEA-770.3
1280 x 768	60, 60RB, 75, 85	x	x	x	x	VESA DMT, CVT 0.98M9/0.98M9-R
1280 x 800	60, 75, 85	X	X	Х	Х	VESA DMT
1280 x 960	60, 75, 85	X	X	Х	Х	VESA DMT
1280 x 1024	60, 75, 85	X	Х	X	Х	VESA DMT, CVT 1.31M4
1366 x 768	60, 60RB	X	Х	Х	Х	VESA DMT
1440 x 900	60, 60RB	X	X	Х	Х	VESA DMT

Technical Specifications – Graphics						
1600 x 900	60, 60RB, 75, 85	x	×	x	x	VESA DMT
1680 x 1050	60, 60RB, 75	х	X	х	X	VESA DMT, CVT 1.76MA/1.76MA-R
1920 x 1080	60	х	X	х	x	VESA DMT, CVT 2.07M9, SMPTE 274M
1920 x 1200	60, 60RB, 75, 85	x	x	x	x	DMT, CVT 2.30MA/2.30MA-R
1600 x 1200	60, 75, 85	X	x	X	x	VESA DMT, 1.92M3
1920 x 1440	60, 75, 85	X	x	X	x	VESA DMT, CVT 2.76M3
2048 x 1536	60,75	X	×	X	x	CVT 3.15M3
2560 x 1440	59.951		x	X	X	CVT 3.69M9-R
2560 x 1600	60, 60RB		x	X	x	VESA DMT, CVT 4.10MA/4.10MA-R
3840 x 2160	24			X	x	CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
3840 x 2160	25			Х	X	CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
3840 x 2160	30		X	Х	X	CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
3840 x 2160	50			X		CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
3840 x 2160	60			Х		CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
4096 x 2160	24			Х	X	CVT-RBv1/v2 (8.85M-R), SMPTE 274M
4096 x 2160	25			X	X	CVT-RBv1/v2 (8.85M-R), SMPTE 274M
4096 x 2160	30			х	x	CVT-RBv1/v2 (8.85M-R), SMPTE 274M
4096 x 2160	50			x		CVT-RBv1/v2 (8.85M-R), SMPTE 274M
4096 x 2160	60			х		CVT-RBv1/v2 (8.85M-R), SMPTE 274M
1920 x 1080	60		X	Х	X	VESA (SMPTE 274M)
1920 x 1080	50		X	х	X	SMPTE 274M
1920 x 1080	30		X	х	X	SMPTE 274M
1920 x 1080	24		X	Х	X	SMPTE 274M
1280 x 720	60		X	х	x	VESA (CEA-770.3)
1280 x 720	50		×	x	×	SMPTE 296M
720 x 480	60		x	×	Х	MHL (CEA-770.2)

AMD Radeon? RX 460 4GB FH PCIe x16 Graphics Card

Memory2GB 128-bit wide frame buffer operating at 1750MHz.Controller Clock SpeedAMD® Radeon? RX 460 GPU operating at up to 1.2GHzMulti-display SupportA maximum of 4 displays are supported by the card.

Graphics /API support DIRECTX 12, Open GL 4.5, Open CL 2.0, AMD Video Coding Engine (VCE) 3.4 and AMD Universal

Video Decoder(UVD)

Output Connectors 1 x Dual-Link DVI-D, 1x DisplayPort?; 1x HDMI

Supported Display Resolutions and Refresh Rates

Note: other resolutions may be available but are not recommended as they may not have been tested and qualified by HP



Technical Specifications – Graphics

		DVI- D	DisplayPort ?		ндмі
Resolution	Refresh Rate*				Standard
640 x 480	60, 75, 85	Х	X	Х	VESA DMT, CVT 0.31M3
720 x 400	70	Х	X	Х	IBM VGA
800 x 600	60, 75, 85	Х	X	X	VESA DMT, CVT0.48M3
1024 x 768	60, 75, 85	Х	X	X	VESA DMT, CVT 0.79M3
1152 x 864	60, 75, 85	Х	X	X	VESA DMT, CVT 0.83MA
1280 x 720	60, 75, 85	Х	X	X	VESA DMT, CVT 0.92M9, CEA-770.3
1280 x 768	60, 60RB, 75, 85	Х	X	X	VESA DMT, CVT 0.98M9/0.98M9-R
1280 x 800	60, 75, 85	Х	X	X	VESA DMT
1280 x 960	60, 75, 85	Х	X	X	VESA DMT
1280 x 1024	60, 75, 85	Х	X	X	VESA DMT, CVT 1.31M4
1366 x 768	60, 60RB	Х	X	х	VESA DMT
1440 x 900	60, 60RB	Х	X	х	VESA DMT
1600 x 900	60, 60RB, 75, 85	Х	X	х	VESA DMT
1680 x 1050	60, 60RB, 75	Х	X	х	VESA DMT, CVT 1.76MA/1.76MA-R
1920 x 1080	60	Х	X	х	VESA DMT, CVT 2.07M9, SMPTE 274M
1920 x 1200	60, 60RB, 75, 85	Х	X	х	DMT, CVT 2.30MA/2.30MA-R
1600 x 1200	60, 75, 85	Х	X	х	VESA DMT, 1.92M3
1920 x 1440	60, 75, 85	Х	X	х	VESA DMT, CVT 2.76M3
2048 x 1536	60, 75	X	X	х	CVT 3.15M3
2560 x 1440	59.951	X	X	х	CVT 3.69M9-R
2560 x 1600	60, 60 RB	X	X	х	VESA DMT, CVT 4.10MA/4.10MA-R
3840 x 2160	24		X	х	CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
3840 x 2160	25		x	х	CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
3840 x 2160	30	X	x	х	CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
3840 x 2160	50		x	X	CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
3840 x 2160	60		x	X	CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
4096 x 2160	24		x	х	CVT-RBv1/v2 (8.85M-R), SMPTE 274M
4096 x 2160	25		X	х	CVT-RBv1/v2 (8.85M-R), SMPTE 274M
4096 x 2160	30		X	x	CVT-RBv1/v2 (8.85M-R), SMPTE 274M
4096 x 2160	50		X	x	CVT-RBv1/v2 (8.85M-R), SMPTE 274M
4096 x 2160	60		X	Х	CVT-RBv1/v2 (8.85M-R), SMPTE 274M

Technical Specification	s – Graphics				
1920 x 1080	60	x	Х	X	VESA (SMPTE 274M)
1920 x 1080	50	x	Χ	Х	SMPTE 274M
1920 x 1080	30	x	Χ	X	SMPTE 274M
1920 x 1080	24	x	Χ	X	SMPTE 274M
1280 x 720	60	x	Χ	X	VESA (CEA-770.3)
1280 x 720	50	x	Χ	Х	SMPTE 296M
720 x 480	60	X	X	X	MHL (CEA-770.2)

NVIDIA® GeForce® GT 730 1GB PCIe x8 HDMI Graphics Card

Memory 1GB GDDR5 64-bit wide frame buffer operating at 2.5GHz.

Controller Clock Speed NVIDIA® Kepler? GPU operating at 901 MHz

Multi-display Support A maximum of 2 displays are supported by the card

Graphics /API support

Supports Microsoft DirectX 12, OpenGL 4.4 and OpenCL 2 API, Shade Model 5 and DirectCompute

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Output Connectors 1 x Dual-Link DVI-I; 1x HDMI; Includes DVI to VGA adapter

Supported Display Resolutions and Refresh Rates

Note: other resolutions may be available but are not recommended as they may not have been tested and qualified by HP

		VGA (DVI- VGA adapter)	DVI-D	HDMI		
Resolution	Refresh Rate*					Standard
640 x 480	60, 75, 85	Х	X	Χ		VESA DMT, CVT 0.31M3
720 x 400	70	Х	X	Х	•	IBM VGA
800 x 600	60, 75, 85	X	X	X	•	VESA DMT, CVT0.48M3
1024 x 768	60, 75, 85	X	X	X	•	VESA DMT, CVT 0.79M3
1152 x 864	60, 75, 85	X	×	X	•	VESA DMT, CVT 0.83MA
1280 x 720	60, 75, 85	X	X	X	•	VESA DMT, CVT 0.92M9, CEA-770.3
1280 x 768	60, 60RB, 75, 85	X	X	X	•	VESA DMT, CVT 0.98M9/0.98M9-R
1280 x 800	60, 75, 85	X	X	X	•	VESA DMT
1280 x 960	60, 75, 85	X	X	X	•	VESA DMT
1280 x 1024	60, 75, 85	X	X	X	•	VESA DMT, CVT 1.31M4
1366 x 768	60, 60RB	X	X	X	•	VESA DMT
1440 x 900	60, 60RB	X	×	X	•	VESA DMT
1600 x 900	60, 60RB, 75, 85	X	X	X	•	VESA DMT
1680 x 1050	60, 60RB, 75	X	X	X	•	VESA DMT, CVT 1.76MA/1.76MA-R
1920 x 1080	60	X	X	X	-	VESA DMT, CVT 2.07M9, SMPTE 274M

Technical Specifica	tions – Graphics					
1920 x 1200	60, 60RB, 75, 85	X	X	X	_	DMT, CVT 2.30MA/2.30MA-R
1600 x 1200	60, 75, 85	X	X	X	•	VESA DMT, 1.92M3
1920 x 1440	60, 75, 85	X	X	X	•	VESA DMT, CVT 2.76M3
2048 x 1536	60,75	X	X	Х	•	CVT 3.15M3
2560 x 1440	59.951		X	Х	•	CVT 3.69M9-R
2560 x 1600	60, 60RB		X	X	•	VESA DMT, CVT 4.10MA/4.10MA-R
3840 x 2160	24			X	•	CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
3840 x 2160	25			X	•	CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
3840 x 2160	30		X	X	•	CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
3840 x 2160	50				•	CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
3840 x 2160	60				•	CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
4096 x 2160	24			Х	•	CVT-RBv1/v2 (8.85M-R), SMPTE 274M
4096 x 2160	25			Х	•	CVT-RBv1/v2 (8.85M-R), SMPTE 274M
4096 x 2160	30			X	•	CVT-RBv1/v2 (8.85M-R), SMPTE 274M
4096 x 2160	50				•	CVT-RBv1/v2 (8.85M-R), SMPTE 274M
4096 x 2160	60				•	CVT-RBv1/v2 (8.85M-R), SMPTE 274M
1920 x 1080	60		X	X	•	VESA (SMPTE 274M)
1920 x 1080	50		X	Х	•	SMPTE 274M
1920 x 1080	30		×	X	•	SMPTE 274M
1920 x 1080	24		X	X	•	SMPTE 274M
1280 x 720	60		X	Х	•	VESA (CEA-770.3)
1280 x 720	50		×	X	•	SMPTE 296M
720 x 480	60		×	X	•	MHL (CEA-770.2)

^{* &}gt;60 refresh rates only for analog (VGA) signaling

NVIDIA® GeForce® GT 730 2GB DP PCIe x8 Graphics Card

Introduction	Get impressive graphics and high resolution dual-display performance in a low profile, PCI Express x8 graphics add-in card based on the NVIDIA® Kepler? Graphics Processor. Improve your everyday PC, Web conferencing, and video or photo editing.
Memory	2GB GDDR5 64-bit wide frame buffer operating at 900 MHz
Controller Clock Speed	NVIDIA® Kepler? GPU operating at 902 MHz
Multi-display Support	A maximum of 4 displays are supported by the card.
Graphics /API support	Supports Microsoft DirectX 12, OpenGL 4.4 and OpenCL 2 APIs, Shade Model 5, UVD 4.2, VCE 2.0, and DirectCompute 11



Technical Specifications – Graphics

1 x Dual-Link DVI-I, 1x DisplayPort?; Includes DVI to VGA adapter

Output Connectors Display Port output is multi-mode capable, support Audio, HBR2 and MST

		VGA (DVI- VGA adapter)	DVI- D	DisplayPort ?	
Resolution	Refresh Rate*				Standard
640 x 480	60, 75, 85	Χ	Х	Χ	VESA DMT, CVT 0.31M3
720 x 400	70	Χ	Х	Χ	IBM VGA
800 x 600	60, 75, 85	Χ	Х	Χ	VESA DMT, CVT0.48M3
1024 x 768	60, 75, 85	X	X	Χ	VESA DMT, CVT 0.79M3
1152 x 864	60, 75, 85	X	Х	X	VESA DMT, CVT 0.83MA
1280 x 720	60, 75, 85	X	Х	X	VESA DMT, CVT 0.92M9, CEA-770.3
1280 x 768	60, 60RB, 75, 85	X	Х	X	VESA DMT, CVT 0.98M9/0.98M9-R
1280 x 800	60, 75, 85	X	Х	X	VESA DMT
1280 x 960	60, 75, 85	X	Х	X	VESA DMT
1280 x 1024	60, 75, 85	X	Х	X	VESA DMT, CVT 1.31M4
1366 x 768	60, 60RB	X	Х	X	VESA DMT
1440 x 900	60, 60RB	X	Х	X	VESA DMT
1600 x 900	60, 60RB, 75, 85	X	Х	X	VESA DMT
1680 x 1050	60, 60RB, 75	X	Х	X	VESA DMT, CVT 1.76MA/1.76MA-R
1920 x 1080	60	X	Х	X	VESA DMT, CVT 2.07M9, SMPTE 274M
1920 x 1200	60, 60RB, 75, 85	X	Х	X	DMT, CVT 2.30MA/2.30MA-R
1600 x 1200	60, 75, 85	X	Х	X	VESA DMT, 1.92M3
1920 x 1440	60, 75, 85	X	Х	X	VESA DMT, CVT 2.76M3
2048 x 1536	60,75	X	Х	X	CVT 3.15M3
2560 x 1440	59.951		Х	X	CVT 3.69M9-R
2560 x 1600	60, 60RB		Х	X	VESA DMT, CVT 4.10MA/4.10MA-R
3840 x 2160	24			X	CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
3840 x 2160	25			X	CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
3840 x 2160	30		Х	X	CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
3840 x 2160	60			X	CVT-RBv1/v2 (8.29M9-R), SMPTE 274M
4096 x 2160	24			Х	CVT-RBv1/v2 (8.85M-R), SMPTE 274M
4096 x 2160	25			Х	CVT-RBv1/v2 (8.85M-R), SMPTE 274M
4096 x 2160	30			Х	CVT-RBv1/v2 (8.85M-R), SMPTE 274M
4096 x 2160	60			Х	CVT-RBv1/v2 (8.85M-R), SMPTE 274M
1920 x 1080	60		X	Х	VESA (SMPTE 274M)
1920 x 1080	50		Х	x	SMPTE 274M

Technical Specification	ons – Graphics			
1920 x 1080	30	x	X	SMPTE 274M
1920 x 1080	24	X	X	SMPTE 274M
1280 x 720	60	X	X	VESA (CEA-770.3)
1280 x 720	50	X	X	SMPTE 296M
720 x 480	60	X	X	MHL (CEA-770.2)
720 x 576	50	X	X	ITU-R BT.1358
640 x 480	60	X	X	CEA (VESA DMT)

^{* &}gt;60 refresh rates only for analog (VGA) signaling



HARD DISK AND SOLID STORAGE

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 16 GB (for Windows 7) and 36 GB (for Windows 8.1/10) of system disk is reserved for the system recovery software.

HP 1 TB 7.2K SATA 6.0Gb/s 2.5"? Hard Disk Drive

Capacity 1,000,204,886,016 bytes

Rotational Speed 7,200 rpm

Interface SATA 6 Gb/s

Buffer Size 32 MB

Logical Blocks 1,953,525,168

Single Track: 2.0 ms

Seek Time (typical reads,

includes controller overhead, Average:

including settling)

Full-Stroke: 25 ms

Height (nominal) 0.374 in/9.5 mm

Media diameter: 2.5 in/63.5 mm

Width (nominal)

Physical size: 2.75 in/70 mm

Operating Temperature 41° to 131° F (5° to 55° C)

*NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

12 ms

Technical Specifications – Hard Disk and Solid State Storage

HP 500 GB 7.2K SATA 6.0Gb/s 2.5"? Hard Disk Drive*

Capacity 500,107,862,016 bytes

Rotational Speed 7,200 rpm

Interface SATA 6 Gb/s

Buffer Size 16 MB

Logical Blocks 976,773,168

Single Track: 2.0 ms

Seek Time (typical reads,

includes controller overhead,

Average:

12 ms

including settling)

Full-Stroke: 25 ms

Height (nominal) 0.267 in/6.8 mm

Media diameter: 2.5 in/63.5 mm

Width (nominal)

Physical size: 2.75 in/70 mm

Operating Temperature 41° to 131° F (5° to 55° C)

*NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

500GB* 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive

Formatted Capacity 500,107,862,016 bytes

Spindle Speed 7,200 rpm

Interface Serial ATA 3.0 (6.0 Gb/s)

Buffer Size 16 MB

Logical Blocks 976,773,168

Single Track: 2.0 ms

Seek Time (average) Average: 11 ms

Full-Stroke: 21 ms

Height (nominal) 1 in/2.54 cm

Media diameter: 3.5 in/8.89 cm

Width (nominal)

Physical size: 4 in/10.2 cm

Operating Temperature 41° to 131° F (5° to 55° C)



HP 1 TB* 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive*

Formatted Capacity 1,000,204,886,016 bytes

Rotational Speed 7,200 rpm

Interface Serial ATA 3.0 (6.0 Gb/s)

Buffer Size 32 MB

Logical Blocks 1,953,525,168

Single Track: 2.0 ms

Seek Time (average) Average: 11 ms

Full-Stroke: 21 ms

Height (nominal) 1 in/2.54 cm

Media diameter: 3.5 in/8.89 cm

Width (nominal)

Physical size: 4 in/10.2 cm

Operating

Temperature

41° to 131° F (5° to 55° C)

HP 2 TB* 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive*

Formatted 2 TB

Capacity

Rotational Speed 7,200 rpm

Interface SATA 6Gb/s NCQ

Cache, 64 MB

Multisegmented

(MB)

Seek Time Read <8.5 ms

(average) Write <9.5 ms

Height 1.028 in/26.11 mm

Width 4.0 in/101.6 mm

Depth 5.787 in/146.99 mm

Weight 1.38 lb/626 g

Operating

32° to 140° F (0° to 60° C) **Temperature**

^{*} For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.



HP 1 TB* SATA 6G 2.5" 8GB Solid State Hybrid Drive (SSHD)*

Formatted Capacity 1 TB

Spindle Speed 5,400 rpm +/- 0.2%

Drive Type Solid State Hybrid Drive (SSHD) technology with NAND Flash

Interface SATA 6 Gb/s

Cache Buffer 64 MB

NAND Flash 8 GB

Commercial Multilevel Cell

(cMLC)

Number of Sectors 976,773,168

Single Track: 2.0 ms

Seek Time (typical reads)

Average: 12 ms

Height 0.374 +/-.008 in (9.5 +/- 0.2 mm)

Width 2.750 +/- 0.010 in (69.85 +/- 0.25 mm)

Length 3.951 +0.008 / -0.010 in (100.35 +0.20 / -0.25 mm)

Weight 0.254 lb/115 g (max)

Operating Temperature 32° to 140° F (0° to 60° C)

* For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 16 GB (for Windows 7) and 36 GB (for Windows 8.1/10) of system disk is reserved for the system recovery software.

HP 500 GB SATA 6G 2.5"? 8GB Solid State Hybrid Drive (SSHD)*

Formatted Capacity 500 GB

Spindle Speed 5,400 rpm +/- 0.2%

Drive Type Solid State Hybrid Drive (SSHD) technology with NAND Flash

Interface SATA 6 Gb/s

Cache Buffer 64 MB

NAND Flash

Commercial Multilevel Cell 8 GB

(cMLC)

Number of Sectors 976,773,168

Technical Specifications – Hard Disk and Solid State Storage

Single Track: 2.0 ms

Seek Time (typical reads)

Average: 12 ms

Height 0.268 +/-.008 in (6.8 +/- 0.2 mm)

Width 2.750 +/- 0.010 in (69.85 +/- 0.25 mm)

Length 3.951 +0.008 / -0.010 in (100.35 +0.20 / -0.25 mm)

Weight 0.209 lb/95 g (max)

Operating Temperature 41° to 131° F (5° to 55° C)

*NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 16 GB (for Windows 7) and 36 GB (for Windows 8.1/10) of system disk is reserved for the system recovery software.

HP 1-TB SATA 6G 3.5"? 8GB Solid State Hybrid Drive (SSHD)*

Formatted Capacity 1 TB

Spindle Speed 7,200 rpm

Drive Type Solid State Hybrid Drive (SSHD) technology with NAND Flash

Interface Serial ATA (SATA)

Cache Buffer 64 MB

NAND Flash

Multilevel Cell (MLC)

8 GB

Number of Sectors 1,953,525,168

Single Track: 2.0 ms

Seek Time (typical reads)

Average: 11 ms

Height 0.783 in / 2.01 cm

Width 4 in / 10.2 cm

Length 5.79 in / 14.7 cm

Weight 0.88 lb/400 g

Operating Temperature 41° to 131° F (5° to 55° C)



500 GB* SATA 2.5" Self-Encrypting (SED) Opal 2 Solid State Drive*

Unformatted Capacity 500GB

Architecture Self-Encrypting (SED) Solid State Drive with 25nm MLC NAND Flash and SATA interface

Interface Serial ATA 2.0 (3.0 Gb/s)

NAND Flash 25nm MLC NAND Flash

Height .275 in/7mm

Width 2.75 in/69.85 mm

Length 3.95 in/100.5 mm

Weight 0.161 lb (73 g)

Bandwidth Performance Sustained Sequential 128k

Read:

Up to 450 MB/s

Sustained Sequential 128k

Write:

Up to 260 MB/s

Random 4k Read: Up to 46K IOPs

Random 4k Write: Up to 56K IOPs

Latency Read: $55 \mu s$

Write: 55 μs

Power SATA power consumption: 160 mW (active average); <85 mW (idle average)

Useful Drive Life 72TB written, up to 40GB/day for 5 years

Operating Temperature: 32° to 158° F (0° to 70° C)

Environmental

(all conditions, non-condensing)

Relative Humidity: 5% to 95%

Shock: 1,500 G/1 ms

256 GB SATA 2.5"? TLC SED SSD Opal 2 Drive*

Informatted Capacity

256 GB

Unformatted Capacity

500,118,192 (User Addressable Sectors)

Architecture

Self-Encrypting (SED) Solid State Drive with NAND Flash and SATA interface.

Trusted Computing Group (TCG) OPAL 2.0 compliant encrypted solid state drive

Interface Serial ATA (6.0 Gb/s)

Form Factor 2.5 inch

Height 6.80 mm ± 0.20

Width 69.85 mm ± 0.25

Length $100.20 \text{ mm} \pm 0.25$

Typical Weight 37.4 g

Bandwidth Performance Sustained Sequential

Read:

Up to 520 MB/s

Sustained Sequential

Write:

Up to 460 MB/s

Power Power consumption: Active: 3.891W; Idle: 0.085W

Mean Time Between Failure

(MTBF)

1,500,000 hours

Environmental Operating Temperature: 32° to 158° F (0° to 70° C)

(all conditions, non-

condensing) Relative Humidity: 5% to 95%

Shock: 1,500 G/0.5 ms

512 GB SATA 2.5"? TLC SED SSD Opal 2 Drive*

512 GB **Unformatted Capacity**

1,000,215,216 (User Addressable Sectors)

Self-Encrypting (SED) Solid State Drive with NAND Flash and SATA interface.

Architecture

Trusted Computing Group (TCG) OPAL 2.0 compliant encrypted solid state drive

Interface Serial ATA (6.0 Gb/s)

Form Factor 2.5 inch

Height 7 mm ± 0.20

Width 69.85 mm ± 0.25

Length 100.20 mm ± 0.25

Typical Weight 37.4 g

Bandwidth Performance Sustained Sequential

Read:

Up to 515 MB/s

Sustained Sequential

Write:

Up to 490 MB/s

Maximum active power: =4,400mW

Power Power consumption: Average power: 70mW

Slumber low power mode: 42mW - 52mW

Mean Time Between Failure

(MTBF)

Up to 1,750,000 hours

Environmental Operating Temperature: 0°C to 70°C (32°F to 158°F)

(all conditions, non-

condensing) Non-operating temperature and storage -55°C to +85°C (-67°F to 185°F)

Operating and non-operating shock 1,500 G/0.5 ms

Technical Specifications – Hard Disk and Solid State Storage

256GB Turbo Drive G2 TLC Solid State Drive

Unformatted Capacity 256 GB

Solid State Drive with TLC NAND Flash and PCIE interface.

Complies with NVMe Standard

Architecture

Power Saving Modes: L1 substates support

Multi Queue support

Interface PCI-E Gen3 x 4

Form Factor M.2 2280

Height 3.73 mm

Width 22.00 ± 0.15 mm

Length $80.00 \pm 0.15 \, \text{mm}$

Weight Up to 8 g

Bandwidth Performance Sustained Sequential

Read:

Up to 2600 MB/s

Sustained Sequential

Write:

Up to 1000 MB/s

Active: Typical 6.1W;

Power Power consumption: Idle: Typical 80mW

L1.2: Typical 5mW

Mean Time Between Failure (MTBF) 1,500,000 hours

Environmental Operating Temperature: 32° to 158° F (0° to 70° C)

(all conditions, non-condensing)

Relative Humidity: 5% to 95%

Shock: 1,500 G/0.5 ms

Technical Specifications – Hard Disk and Solid State Storage

512GB Turbo Drive G2 TLC Solid State Drive

Unformatted Capacity 512 GB

Solid State Drive with TLC NAND Flash and PCIE interface.

Complies with NVMe Standard

Architecture

Power Saving Modes: L1 substates support

Multi Queue support

Interface PCI-E Gen3 x 4

Form Factor M.2 2280

Height 3.73 mm

Width 22.00 ± 0.15 mm

Length 80.00 ± 0.15 mm

Weight Up to 8 g

Bandwidth Performance Sustained Sequential

Read:

Up to 2600 MB/s

Sustained Sequential

Write:

Up to 1200 MB/s

Active: Typical 6.1W;

Power Power consumption: Idle: Typical 80mW

L1.2: Typical 5mW

Mean Time Between Failure (MTBF) 1,500,000 hours

Environmental Operating Temperature: 32° to 158° F (0° to 70° C)

(all conditions, non-condensing)

Relative Humidity: 5% to 95%

Shock: 1,500 G/0.5 ms

Technical Specifications – Hard Disk and Solid State Storage

1TB Turbo Drive G2 TLC Solid State Drive

Unformatted Capacity 1 TB

Solid State Drive with TLC NAND Flash and PCIE interface.

Complies with NVMe Standard

Architecture

Power Saving Modes: L1 substates support

Multi Queue support

Interface PCI-E Gen3 x 4

Form Factor M.2 2280

Height 3.73 mm

Width 22.00 ± 0.15 mm

Length 80.00 ± 0.15 mm

Weight Up to 8 g

Bandwidth Performance Sustained Sequential

Read:

Up to 2600 MB/s

Sustained Sequential

Write:

Up to 1400 MB/s

Active: Typical 6.1W;

Power Power consumption: Idle: Typical 80mW

L1.2: Typical 5mW

Mean Time Between Failure (MTBF) 1,500,000 hours

Environmental Operating Temperature: 32° to 158° F (0° to 70° C)

(all conditions, non-condensing)

Relative Humidity: 5% to 95%

Shock: 1,500 G/0.5 ms



128GB SATA 2.5" Value (Non-SED) Solid State Drive

Unformatted Capacity 128 GB

Architecture TLC NAND Flash

Interface SATA 3.2 (6.0 Gb/s)

Form Factor 2.5 inch

Dimensions (W x D x H) 6.98 x 10.05 x 0.7 cm

Weight 31g

Bandwidth Performance Sustained Sequential

Read:

Up to 510 MB/s

Sustained Sequential

Write:

Up to 330 MB/s

Random Read: Up to 38K IOPs

Random Write: Up to 70K IOPs

Power DC power requirement: 5 VDC 5%-100 mV ripple p-p

Total power 50mW (active); 20mW (idle)

consumption:

Useful Drive Life 72TB written, up to 40GB/day for 5 years

Environmental Operating Temperature: 32° to 158° F (0° to 70° C)

(all conditions, non-condensing)

Relative Humidity: 5% to 95%

Shock: 1,500 G/0.5 ms



256GB SATA 2.5" Value (Non-SED) Solid State Drive

Unformatted Capacity 256 GB

Architecture TLC NAND Flash

Interface SATA 3.2 (6.0 Gb/s)

Form Factor 2.5 inch

Dimensions (W x D x H) 6.98 x 10.05 x 0.7 cm

Weight 31g

Bandwidth Performance Sustained Sequential

Read:

Up to 510 MB/s

Sustained Sequential

Write:

Up to 330 MB/s

Random Read: Up to 38K IOPs

Random Write: Up to 70K IOPs

Power DC power requirement: 5 VDC 5%-100 mV ripple p-p

Total power 50mW (active); 20mW (idle)

consumption:

Useful Drive Life 72TB written, up to 40GB/day for 5 years

Environmental Operating Temperature: 32° to 158° F (0° to 70° C)

(all conditions, non-condensing)

Relative Humidity: 5% to 95%

Shock: 1,500 G/0.5 ms



256GB SATA 2.5"? TLC Solid State Drive

Formatted Capacity 256 GB

Architecture Solid State Drive with SATA interface; ATA 8 Compliant and SATA 2.6 compliant

Interface Serial ATA 3 (6.0 Gb/s)

Form Factor 2.5 inch

Height 7 mm ± 0.20

Width 69.85 mm ± 0.25

Length 100.2 mm ± 0.25

Weight (typical) 36.5 g (+2)

Data Transfer Rate Sequential Read Up to 500 MB/s

(128k Sequential)

Sequential Write Up to 455 MB/s

Read: 95 mW

Power Watts

Power consumption

Write: 95 mW

(avg): Standby: 70 mW

DEVSLP: <7 mW

Environmental Operating Temperature: 32° to 158° F (0° to 70° C)

(all conditions, non-

condensing) Relative Humidity: 5% to 95%

Shock (2 m Sec half-sine): 1500 G peak 0.5ms (operating)



512 GB SATA 2.5"? TLC Solid State Drive*

Formatted Capacity 512 GB

Architecture Solid State Drive with SATA interface; ATA 8 Compliant and SATA 2.6 compliant

Interface Serial ATA 3 (6.0 Gb/s)

Form Factor 2.5 inch

Height 7 mm ± 0.20

Width 69.85 mm ± 0.25

Length 100.2 mm ± 0.25

Weight (typical) 36.5 g (+2)

Data Transfer Rate Sequential Read Up to 500 MB/s

(128k Sequential)

Sequential Write Up to 455 MB/s

Read: 95 mW

Power Watts Power consumption Write: 95 mW

(avg): Standby: 70 mW

DEVSLP: <7 mW

Environmental Operating Temperature: 32° to 158° F (0° to 70° C)

(all conditions, non-

condensing) Relative Humidity: 5% to 95%

Shock (2 m Sec half-sine): 1500 G peak 0.5ms (operating)

Technical Specifications - Removable Storage

OPTICAL DRIVES

HP 9.5mm G3 800/600/400 SFF G4 400 SFF/MT DVD-Writer

Height 12.7mm height

Orientation Either horizontal or vertical

Interface type SATA/ATAPI

Disc recording capacity Up to 8.5 GB DL or 4.7 GB standard

Dimensions (W x D x H) 5.04 x 5.0 x 0.5 in (128 x 127 x 12.7 mm) without bezel

Weight (max) 0.42 lb (190 g)

DVD-R DL Up to 6X

DVD+R Up to 8X

DVD+RW Up to 8X

DVD+R DL Up to 6X

Write speeds

DVD-R Up to 8X

DVD-RW Up to 6X

CD-R Up to 24X

CD-RW Up to 24X

DVD-RW, DVD+RW Up to 8X

DVD-R DL, DVD+R DL Up to 8X

DVD+R, DVD-R Up to 8X

Read speeds DVD-ROM DL, DVD-ROM Up to 8X

CD-ROM, CD-R Up to 24X

CD-RW Up to 24X

Random DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical)

Full Stroke DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical)

Access time

(typical reads, including Stop Time 6 seconds (typical)

settling)
Source Slimline SATA DC power receptacle

DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p

Power DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)

Temperature 41° to 122° F (5° to 50° C)

Relative Humidity 10% to 80%

Environmental conditions Maximum Wet Bulb 84° F (29° C)

(operating - non-condensing) Temperature



Technical Specifications - Removable Storage

HP 9.5mm G3 800/600/400 SFF G4 400 SFF/MT DVD-ROM

Height 12.7mm

Orientation Either horizontal or vertical

Interface type SATA/ATAPI

Dimensions (W x D x H) 5.04 x 5.0 x 0.5 in (128 x 127 x 12.7 mm) without bezel

Weight (max) Up to 0.37 lb (170 g) without bezel

DVD+R/-R/+RW/

-RW/+R DL /-R DL

Read speeds DVD-ROM Up to 8X

CD-ROM, CD-R Up to 24X

CD-RW Up to 24X

Access time Random DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical)

(typical reads, including

settling) Full Stroke DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical)

Source Slimline SATA DC power receptacle

Up to 8X

Power DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p

DC Current 5 VDC - <1000 mA typical, < 1600 mA maximum

Temperature 41° to 122° F (5° to 50° C)

Environmental (all Relative Humidity 10% to 80%

conditions non-condensing)

Maximum Wet Bulb

84° F (29° C)

Maximum wet Bulb 84°

Temperature (operating)

Technical Specifications – Networking

System Memory Support

The HP ProDesk 400 Business PC supports the 6th &7th generation Intel® Core? processor family. Based on a new PC micro-architecture, the processor is designed for a two-chip platform consisting of a processor and Platform Controller Hub (PCH). The 6th generation Intel® Core? processor includes an Integrated Memory Controller (IMC). The IMC supports DDR4 protocols with two independent, 64-bit wide channels each accessing one or two DIMMs.

- Two channels of non-ECC DDR4 unbuffered dual in-line memory modules (DIMM) or DDR4 unbuffered small outline dual in-line memory modules (SO-DIMM) with a maximum of two DIMMs per channel
- Single-channel and dual-channel memory organization modes
- Data burst length of eight for all memory organization modes
- Memory data transfer rates of up to 2400 MT/s; actual supported data transfer rate determined by the configured processor.
- 64-bit wide channels
- DDR4 system memory I/O voltage of 1.2V

Platform Memory Support

- The Microtower (MT) and Small Form Factor (SFF) platform supports up to two (2) industry-standard DDR4-SDRAM DIMMs.
- The DM platform supports up to two (2) industry-standard DDR4-SDRAM SO-DIMMs.

CAUTION: You must shut down the computer and disconnect the power cord before adding or removing memory modules. Regardless of the power-on state, voltage is always supplied to the memory modules as long as the computer is plugged in to an active AC outlet. Adding or removing memory modules while voltage is present may cause irreparable damage to the memory modules or system board.

NOTE: For systems configured with more than 3 GB of memory and a 32-bit operating system, all memory may not be available due to system resource requirements. Addressing memory above 4 GB requires a 64-bit operating system.

NetworkING

Realtek RTL8111HSH-CG GbE				
10/100/1000 Ethernet Feature NIC		10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) IEEE 802.3az EEE (Energy Efficient Ethernet) Jumbo Frame 9K Auto MDI/MDIX Crossover cable detection		
	Power Management	ACPI compliant - multiple power modes Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption		
	Performance Features	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling		
	Manageability	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot		



Technical Specifications – Networking

Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30))

Comprehensive diagnostic and configuration software suite

Virtual Cable Doctor for Ethernet cable status

Interface PCI Express 1.1 x1 to fully support ASPM LOs/L1 and CLKREQ

NIC Device Driver

Name

PCIe GBE Ethernet Family Controller

Intel® Ethernet I210-T1 Gigabit Network Adapter

Connector RJ-45

System Interface PCI Express x1

Controller Intel® I210 Gigabit Ethernet Controller

Memory Integrated Dual 48K configurable transmit receive FIFO Buffers

Data rates supported 10/100/1000 Mbps

802.1P 802.1Q 802.2 802.3

IEEE Compliance 802.3 802.3AB

802.3u

802.3x flow control

Bus architecture PCI-E 2.1

Data path width X1, 250 MB/s, Bi-directional interface

Data transfer modeBus-master DMA

Hardware certifications FCC, B, CE, TUV-c, TUVus Mark Canada and United States, TUV-GS Mark for European

Union

Power requirement Aux 3.3 V, 3.0 Watts in 1000 base-T and 1.0 Watts in 100 Base-T

Yes

Boot ROM support 10BASE-T (half-duplex) 10 Mbps

10BASE-T (full-duplex) 20 Mbps

Technical Specifications - Networking

10BASE-T (half-duplex) 10 Mbps

10BASE-T (full-duplex) 20 Mbps

Network transfer rate 100BASE-TX (half-duplex) 100 Mbps

100BASE-TX (full-duplex) 200 Mbps

1000BASE-T (full-duplex) 2000 Mbps (actual rate limited by PCI bus)

Operating Temperature: 32° to 132° F (0° to 55° C)

Environmental

Operating Humidity: 85% at 131° F (55° C)

Management WOL, PXE, DMI, WFM 2.0

Data Rates

Intel® 7265 802.11ac 2x2 DualBand Combo PCIe x1 Card

Wireless LAN Standards IEEE 802.11a

IEEE 802.11b
IEEE 802.11g
IEEE 802.11n
IEEE 802.11ac
Wi-Fi certified

InteroperabilityWi-Fi certifiedFrequency Band802.11b/g/n

• 2.402 - 2.482 GHz

Note:

The FCC has declared as of January 1, 2015 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

otnerwise disable

802.11a/n

• 4.9 - 4.95 GHz (Japan)

• 5.15 - 5.25 GHz

• 5.25 - 5.35 GHz

• 5.47 - 5.725 GHz

• 5.825 - 5.850 GHz

Note: Indonesia no support this band)

• 802.11b: 1, 2, 5.5, 11 Mbps

• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps

• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps

• 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)

Modulation Direct Sequence Spread Spectrum

BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM

Security¹ • IEEE and WiFi compliant 64 / 128 bit WEP encryption

for a/b/g mode only

• AES-CCMP: 128 bit in hardware

802.1x authentication

• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

WPA2 certification

Technical Specifications - Networking

IEEE 802.11i
Cisco Certified Extensions, all versions through CCX4 and CCX Lite
WAPI
Ad-hoc (Peer to Peer)

Network Architecture Ad-hoc (Peer to Peer)

Models Infrastructure (Access Point Required)

Roaming IEEE 802.11 compliant roaming between access points

• 802.11b: +16dBm minimum
• 802.11g: +14dBm minimum
• 802.11a: +14dBm minimum

802.11n HT20(2.4GHz): +13dBm minimum
802.11n HT40(2.4GHz): +13dBm minimum
802.11n HT20(5GHz): +12dBm minimum
802.11n HT40(5GHz): +12dBm minimum
802.11ac 80MHz(5GHz): +11dBm minimum

Power ConsumptionTransmit:2.0 W (max)

Receive: 1.6 W (max)

Idle mode (PSP): 180 mW (WLAN Associated)
Idle mode: 60 mW (WLAN unassociated)

Radio disabled: 30 mW

Power Management ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity³ 802.11b, 1Mbps : -94dBm maximum

802.11b, 11Mbps: -86dBm maximum 802.11g, 6Mbps: -88dBm maximum 802.11g, 54Mbps: -74dBm maximum 802.11a, 6Mbps: -86dBm maximum 802.11a, 54Mbps: -72dBm maximum 802.11n, MCS07: -69dBm maximum 802.11n, MCS15: -66dBm maximum 802.11ac, 1SS, MCS-0: -86dBm maximum 802.11ac, 1SS, MCS-0: -83dBm maximum

802.11ac, 2SS, MCS-9: -58dBm maximum

Antenna type High efficiency antenna with spatial diversity, mounted in the

display enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth

communications

Form Factor PCI-Express M.2 MiniCard

Dimensions Type 2230 : 2.3 x 22.0 x 30.0 mm

Or

Type 1630: 2.3 x 16.0 x 30.0 mm

Weight Type 2230 : 2.8g

Or

Type 1630 : 2g

Operating Voltage 3.3v +/- 9%

Humidity

Altitude

TemperatureOperating 14° to 158° F (-10° to 70° C)
Non-operating -40° to 176° F (-40° to 80° C)

Operating 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing)

Operating 0 to 10,000 ft (3,048 m) Non-operating 0 to 50,000 ft (15,240 m)

LED Activity LED Amber - Radio OFF; LED White - Radio ON

Technical Specifications – Networking

Check latest software/driver release for updates on supported security features.

Maximum output power may vary by country according to local regulations.

Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

HP Integrated Module with Bluetooth 4.2 Wireless Technology

Bluetooth Specification 4.2 Compliant

Frequency Band 2402 to 2480 MHz

Number of Available Channels 79 (1 MHz) available channels

Data Rates and Throughput 3 Mbps data rate; throughput up to 2.17 Mbps

Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric or 1306.9 kbps symmetric

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth

device with a maximum transmit power of +4 dBm for BR and EDR.

Receiver Sensitivity Modulation 0.01% BER 0.001% BER

GFSK -80 dBm -70 dBm
p/4-DQPSK -80 dBm -70 dBm
8DPSK -80 dBm -70 dBm

Power Consumption Peak (Tx) 330 mW

Peak (Rx) 230 mW

Selective Suspend 17 mW

Range Up to 33 ft (10 m)
Electrical Interface USB 2.0 compliant

Bluetooth Software Supported

Link Topology

Certifications

Microsoft Windows Bluetooth Software

Electrical Interface
Bluetooth Software Supported

Security

Point to Point, Multipoint Pico Nets up to 7 slaves

Full support of Bluetooth Security Provisions

Power Management Microsoft Windows ACPI, and USB Bus Support

Power Management Self-configurable to optimize power conservation in all operating

Certifications modes, including Standby, Hold, Park, and Sniff

Security All necessary regulatory approvals for supported countries,

including:

Certifications FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Bluetooth Profiles Supported

Power ManagementETS 300 328, ETS 300 826CertificationsLow Voltage Directive IEC950

UL, CSA, and CE Mark
Serial Port Profile (SPP)¹

Service Discovery Application Profile (SDAP)

Dial-Up Networking (DUN)^{1,2}

Generic Object Exchange Profile (GOEP)1,2

Object Push Profile (OPP)^{1,2}
File Transfer Profile (FTP)
Synchronization Profile (SYNC)

Bluetooth Profiles Supported H

files Supported Hard Copy Cable Replacement (HCRP)^{1,2}
Personal Area Networking Profile (PAN)^{1,2}

Human Interface Device Profile (HID)^{1,2}

FAX Profile (FAX)

Basic Imaging Profile (BIP)² Headset Profile (HSP) Hands Free Profile (HFP)



Technical Specifications – Networking

Advanced Audio Distribution Profile (A2DP)

Intel 3168 802.11ac with PCIe x1 WLAN/ Bluetooth® Combo*

Wireless LAN Standards

IEEE 802.11b
IEEE 802.11g
IEEE 802.11n
IEEE 802.11ac

Interoperability

Wi-Fi certification

Frequency Bands

802.11b/g/n 2.402 - 2.482 GHz

Note:

The FCC has declared as of January 1, 2015 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable

those channels.

802.11a/n 4.9 - 4.95 GHz (Japan)

5.15 - 5.25 GHz 5.25 - 5.35 GHz 5.47 - 5.725 GHz 5.825 - 5.850 GHz

Note: Indonesia only supports 5.725 - 5.825 GHz (CH149 - CH161)

Data Rates

- 802.11b: 1, 2, 5.5, 11 Mbps
- 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
- 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
- 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)
- 802.11ac : MCS0 ~ MCS7, (1SS) (20MHz, 40MHz, and 80MHz)

Modulation

Direct Sequence Spread Spectrum

BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM

Security¹

- IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only
- AES-CCMP: 128 bit in hardware
- 802.1x authentication
- WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
- WPA2 certification
- IEEE 802.11i
- Cisco Certified Extensions, all versions through CCX4 and CCX Lite
- WAPI

Network Architecture Models Ad-hoc (Peer to Peer)

Infrastructure (Access Point Required)

¹ Check latest software/driver release for updates on supported security features.

Technical Specifications – Networking

Roaming

802.11r Fast Roaming

Output Power²

- 802.11b: +16dBm minimum802.11g: +14dBm minimum
- 802.11a: +14dBm minimum
- 802.11n HT20(2.4GHz): +14dBm minimum
 802.11n HT40(2.4GHz): +12dBm minimum
 802.11n HT20(5GHz): +14dBm minimum
- 802.11n HT40(5GHz): +12dBm minimum
 802.11ac 80MHz(5GHz): +11dBm minimum

Power Consumption

Transmit: 2.0 W (max)
Receive: 1.6 W (max)

Idle mode (PSP): 180 mW (WLAN Associated)
Idle mode: 50 mW (WLAN unassociated)
Connect Standby: 10 mW (WLAN+BT)

Radio disabled: 5 mW

Power Management

ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity³

802.11b, 1Mbps: -94dBm maximum
802.11b, 11Mbps: -86dBm maximum
802.11g, 6Mbps: -88dBm maximum
802.11g, 54Mbps: -74dBm maximum
802.11a, 6Mbps: -88dBm maximum
802.11a, 54Mbps: -74dBm maximum
802.11a, 54Mbps: -74dBm maximum
802.11n, MCS07: -69dBm maximum
802.11n, MCS15: -66dBm maximum
802.11ac, 1SS, MCS-0: -86dBm maximum
802.11ac, 2SS, MCS-0: -83dBm maximum
802.11ac, 2SS, MCS-0: -83dBm maximum
802.11ac, 2SS, MCS-9: -58dBm maximum

Antenna type

High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications

Form Factors

PCI-Express M.2 MiniCard

Dimensions

Type 2230 : 2.3 x 22.0 x 30.0 mm

Or

Type 1630: 2.3 x 16.0 x 30.0 mm

Weight

Type 2230: 2.8g

Ωr

Type 1630: 2g

Operating Voltage

3.3v +/- 9%

² Maximum output power may vary by country according to local regulations.

³ Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).



Technical Specifications - Networking

Operating: 14° to 158° F (-10° to 70° C) **Temperature** 14° to 158° F (-10° to 70° C)

Non-operating: -40° to 176° F (-40° to 80° C)

Humidity Operating: 10% to 90% (non-condensing)

Non-operating: 5% to 95% (non-condensing)

Operating: 0 to 10,000 ft (3,048 m)

Non-operating: 0 to 50,000 ft (15,240 m)

LED Amber - Radio OFF; LED White - Radio ON

HP Integrated Module with Bluetooth 4.0/4.1/4.2 Wireless Technology

Bluetooth Specification 4.0/4.1/4.2 Compliant

Frequency Band 2402 to 2480 MHz

Number of Available

Channels

LED Activity

Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)

Data Rates and Throughput

Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps

BLE: 1 Mbps data rate; throughput up to 0.2 Mbps

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or

864 kbps symmetric (3-EV5)

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth device with a maximum

transmit power of + 4 dBm for BR and EDR.

Receiver Sensitivity

Legacy

Modulation	0.01% BER	0.001% BER
GFSK	-80 dBm	-70 dBm
p/4-DQPSK	-80 dBm	-70 dBm
8DPSK	-80 dBm	-70 dBm

Power Consumption Peak (Tx) 330 mW

Peak (Rx) 230 mW

Selective Suspend 17 mW

Range Legacy Up to 33 ft (10 m)

BLE Up to 99 ft (30 m)

Electrical Interface USB 2.0 compliant

Bluetooth Software

Supported Link Topology Microsoft Windows Bluetooth Software

^{*} Wireless access point and Internet service required and not included. Availability of public wireless access points limited.

Technical Specifications – Networking

Electrical Interface Bluetooth Software Point to Point, Multipoint Pico Nets up to 7 slaves

Supported Security

Full support of Bluetooth Security Provisions

Power Management Certifications

Microsoft Windows ACPI, and USB Bus Support

Self-configurable to optimize power conservation in all operating modes, including Standby,

Hold, Park, and Sniff

Security All necessary regulatory approvals for supported countries, including:

Certifications

FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Bluetooth Profiles

Supported

Power Management

Certifications

ETS 300 328, ETS 300 826

Low Voltage Directive IEC950

Certifications **Bluetooth Profiles** UL, CSA, and CE Mark

Serial Port Profile (SPP)1 **Supported**

Service Discovery Application Profile (SDAP)

Dial-Up Networking (DUN)^{1,2}

Generic Object Exchange Profile (GOEP)1,2

Object Push Profile (OPP)1,2

Hard Copy Cable Replacement (HCRP)1,2 Personal Area Networking Profile (PAN)1,2 Human Interface Device Profile (HID)1,2

Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

Audio Video Remote Control Profile (AVRCP)

Bluetooth V4.1/V4.2 support V4.1: ESR5/6/7 compliant

feature

V4.2: ESR8 compliant, LE Secure Connection - Basic.

Technical Specifications – Audio

AUDIO

High Definition Audio - MT/SFF/DM

Type Integrated

HD Stereo Codec Conexant CX20632

Audio I/O Ports Headset connector supports a CTIA style headset and is re-taskable as a Line-in, Line-out,

Microphone-in or Headphone-out port

Rear Line-In can be retasked to function as a microphone input

Rear Line-Out

Front Headphone-Out

All ports are 3.5mm and support stereo (see above tables for system configurations)

Internal Speaker Amplifier 2W class D mono amplifier for the internal speaker only. External speakers must be powered

externally.

Multi-streaming Capable Playback multi-streaming can be enabled in the audio control panel to allow independent

audio streams to be sent to/from the front and rear jacks or integrated speaker.

Sampling Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1

kHz to 192 kHz for DAC and 44.1 kHz to 96 kHz for ADC

Wavetable Syntheses Yes - Uses OS soft wavetable

Analog Audio Yes

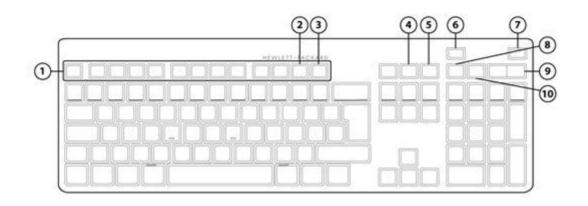
of Channels on Line-Out Stereo (Left & Right channels)

Internal Mono Speaker Yes

Technical Specifications - Input/Output Devices

Input/Output Devices

HP Conferencing Keyboard



1. Function Keys

2. F11 Lync or Skype for Business Contact list *

3. F12 Lync or Skype for Business Calendar **

4. Share Screen

5. Stop Webcam

6. End/Decline a Call

7. Answer a Call

8. Microphone Mute

9. Volume Up/Down

10. Audio Mute

Dimensions (H x L x W) 0.85 x 17.34 x 6.10 in (2.16 x 44.05 x 15.50 cm)

Weight 24.69 oz. (700 g)

Connectivity USB cable

Keys 110 (US) Layout, 111 (EU) Layout - depending upon country

Feature Summary Full-size ultra-quiet keyboard with numerical pad and 12 function keys

One-touch simplicity for Microsoft Lync or Skype for Business calls with dedicated keys and LED $\,$

light indicators

Illuminated keys Incoming Call - Blinks Green

Call in progress -Green Microphone Mute - Orange Audio Mute - Orange Screen Sharing - Orange Stop Webcam - Orange

Other Call control keys End/Decline Call

Volume up and down rocker key

Microsoft Lync/Outlook Fn+F12 - Lync or Skype for Business Calendar will open. If Lync or Skype for Business is not

^{*}Microsoft Lync 2013, or Skype for Business, or Microsoft Outlook 2013 Contact list

^{**}Microsoft Lync 2013, or Skype for Business, or Microsoft Outlook 2013 Calendar

Technical Specifications - Input/Output Devices

available will bring Outlook Calendar *

Fn+F11 - Lync or Skype for Business Contact will open. If Lync or Skype for Business is not available will bring Outlook Contact list *

* Fn+11 and Fn+12 function keys are not supported in Microsoft Windows 8.x Metro mode

Functions Keys Fn+F10 - System Settings

Fn+F9 - Devices Fn+F8 - Search Fn+F7 - Blank

Fn+F6 - Up Brightness Adjustment Fn+F5 - Down Brightness Adjustment

Fn+F4 - Display Options Fn+F3 - File Explorer Fn+F2 - System Lock Fn+F1 - System Sleep

System requirements Available USB port

Windows 7, Windows 8.x, and Windows 10

Server: Microsoft Lync Server 2010 or 2013 and Skype for Business Server 2015 Client: Microsoft Lync 2013 version 15.0.46xx or newer or Skype for Business

Notes:

 Limited support for Microsoft Lync 2010, Microsoft Lync 2013 Basic and Microsoft Metro Mode

Screen brightness functions supported in select HP systems

Approvals FCC; CE; ACA(C-tick); EAC

EMC UL, CE Mark

Product Safety

HP USB PS/2 Washable Keyboard

Keys 104 (US) Layout, 105 (EU) layout - depending upon

country

Physical Characteristics
Dimensions (W x L x H)
6.62 x 17.67 x 1.38 in (168 x 449 x 35 mm)

Weight 1.7 lb (0.77 kg) minimum

Operating voltage + 5VDC ±5%

Power consumption 50-mA maximum (with three LEDs ON)

System interface USB Type A plug connector **Electrical**

ESD CE level 4, 15-kV air discharge

EMI - RFI Conforms to FCC rules for a Class B computing device

Microsoft PC 99 - 2001 Functionally compliant

Technical Specifications – Input/Output Devices

	Keycaps	Stepped -profile design		
	Switch actuation	55-g nominal peak force with tactile feedback		
	Switch life	20 million keystrokes		
Mechanical	Switch type	Contamination-resistant switch membrane		
Mechanicat	Key-leveling mechanisms	For all double-wide and greater-length keys		
	Cable length	7 ft (2.2 m)		
	Microsoft PC 99 - 2001	Mechanically compliant		
	Acoustics	43-dBA maximum sound pressure level		
	Operating temperature	50° to 122° F (10° to 50° C)		
	Non-operating temperature	4° to 149° F (-20° to 65° C)		
	Operating humidity	10% to 95% (non-condensing at ambient)		
	Non-operating humidity	0% to 95% (non-condensing at ambient)		
Environmental	Operating shock	40 g, six surfaces		
Environmental	Non-operating shock	80 g, six surfaces		
	Operating vibration	2-g peak acceleration		
	Non-operating vibration	4-g peak acceleration		
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence		
	Drop (in box)	42 in (107 cm) on concrete, 16-drop sequence		
Operating system support	Windows® 7, Windows Vista, Windows XP Professional			
Approvals	UL, cUL, FCC, CE, TUV GS, VCCI, BSMI, C-Tick, KCC, USB-IF, WHQL, EN/IEC 60601-1, IP66/NEMA4X			
Ergonomic compliance	ANSI HFS 100, ISO 9241-4, and TUVGS			

HP USB Business Slim Smartca	rd Ke	vboard
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Electrical

Keys 104, 105, 109 layout

(depending upon country

Physical Characteristics Dimensions 0.78 x 5.68 x 17.34 in (14.45 x 1.98 x 440.6 cm)

 $W \times D \times H$)

System interface

Weight 1.32 lb (0.6± 0.1 kg)

Operating voltage 5V
Power consumption 200 mA

ESD Air 12.5kV / Contact 8kV

EMI - RFI under 3dB

Microsoft PC 99 - 2001 Conforms to FCC rules for a Class B computing device

USB Interface

Keycaps Low-profile design

Switch actuation 60±15g nominal peak force with tactile feedback

Switch life 10 million keystrokes (Life tester)

Mechanical

Switch type Contamination-resistant switch membrane

Key-leveling mechanisms For all double-wide and greater-length keys

Cable length 6 ft (1.8 m)

Environmental

Technical Specifications - Input/Output Devices

Acoustics 43-dBA maximum sound pressure level

Operating temperature 50° to 122° F (10° to 50° C)
Non-operating temperature -22° to 140° F (-30° to 60° C)

Operating humidity 10% to 90% (non-condensing at ambient)
Non-operating humidity 20% to 80% (non-condensing at ambient)

Operating shock 40 g, six surfaces
Non-operating shock 80 g, six surfaces

Operating vibration 2-g peak acceleration
Non-operating vibration 4-g peak acceleration

Drop 26 in (66 cm) on carpet, six-drop sequence

(out of box)

Drop 30 in (76.2 cm) on concrete, 16-drop sequence

(in box)

Support All ISO 7816 smart cards

Interface Reads from and writes to all ISO7816-1, 2, 3, 4 memory

and microprocessor smart cards (T=0, T=1)

Chipset IDENTIVE CLOUD 2190 F
Standard APIs supported PC/SC, EMV2000, CT-API

Power USB Port

Short circuit detection (protects smart card and reader)
Power supply compliant with ISO7816 and EMV (5V, 60

mA)

SmartCard Function
Supports 3-V and 5-V cards
Power consumption
100-mA maximum draw

Communication From card 9600 bps to 330,000 bps

From computer 12 Mbps (USB transfer speed)

Landing mechanism Contact device Friction contact

Card insertions rating Up to 100,000 insertion cycles

Interface modes CCID protocol
Reader performance interface USB connection

Electro-magnetic standards Europe 2004/108/EC

USA USAFCC part 15

Approvals CE Marking; TUV; EAC; FCC; cULus/CSAus; ICES; RCM; VCCI; KCC; BSMI

Ergonomic Compliance ISO 9241-410, TUV GS

Kit Contents Keyboard, I/O Security and Documentation CD, warranty card

HP USB Business Slim Keyboard

104, 105, 106, 107, 109 layout (depending upon

country)

Physical characteristics171.97 x 68.35 x 8.27 in (436.8± 1.5 x 137.6± 1.0 x Dimensions (L x W x H)

^(× H) 21.0± 1.0 cm)

Weight 1.32 lb (0.6± 0.08 kg)

Technical Specifications – Input/Output Devices

	Operating voltage	+ 4.4 - 5.25VDC		
	Power consumption	50-mA maximum (with 5 VDC power supplied and three LEDs ON)		
	System interface	USB Type A plug connector		
Electrical	ESD	Contact Discharge: 2, 4,6,8KV		
		Air Discharge: 2, 4, 8,10,12.5KV		
	EMI - RFI	Conforms to FCC rules for a Class B computing device		
	Microsoft® PC 99 - 2001	Functionally compliant		
	Keycaps	Low-profile design		
	Switch actuation	60±12.5g nominal peak force with tactile feedback		
	Switch life	10 million keystrokes (Life tester)		
Mechanical	Switch type	Contamination-resistant switch membrane		
	Key-leveling mechanisms	For all double-wide and greater-length keys		
	Cable length	6 ft (1.8 m)		
	Microsoft PC 99 - 2001	Mechanically compliant		
	Acoustics	43-dBA maximum sound pressure level		
	Operating temperature	50° to 122° F (10° to 50° C)		
	Non-operating temperature	-22° to 140° F (-30° to 60° C)		
	Operating humidity	10% to 90% (non-condensing at ambient)		
	Non-operating humidity	20% to 80% (non-condensing at ambient)		
Environmental	Operating shock	40 g, six surfaces		
	Non-operating shock	80 g, six surfaces		
	Operating vibration	2-g peak acceleration		
	Non-operating vibration	4-g peak acceleration		
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence		
	Drop (in box)	30 in (76.2 cm) on concrete, 16-drop sequence		
Approvals	UL, FCC, CE Mark, TUV, TUV GS, V(CCI, BSMI, C-Tick, KC		
Ergonomic compliance	ANSI HFS 100, ISO 9241-4, and TUVGS			
I				

Electrical

Technical Specifications - Input/Output Devices

Kit contents Keyboard Installation Guide

Warranty Card Safety and Comfort Guide

HP PS/2 Business Slim Keyboard

104, 105, 106, 107, 109 layout (depending upon

country)

Physical Characteristics 171.97 x 68.35 x 8.27 in (436.8± 1.5 x 137.6± 1.0 x

21.0± 1.0 cm)

Weight 1.32 lb (600± 80 g)

Operating voltage + 4.4 - 5.25VDC

Power consumption 50-mA maximum (with 5 VDC power supplied and three

LEDs ON

System interface PS/2 6-pin mini din connector

Contact Discharge: 2, 4,6,8KV ESD

Air Discharge: 2, 4, 8,10,12.5KV

EMI - RFI Conforms to FCC rules for a Class B computing device

Microsoft PC 99 - 2001 Functionally compliant

Keycaps Low-profile design

Switch actuation 60±12.5g nominal peak force with tactile feedback

Switch life 10 million keystrokes (Life tester)

Switch type Contamination-resistant switch membrane

Key-leveling mechanisms For all double-wide and greater-length keys

Cable length 6 ft (1.8 m)

Microsoft PC 99 - 2001 Mechanically compliant

Technical Specifications - Input/Output Devices

Acoustics 43-dBA maximum sound pressure level

Operating temperature 50° to 122° F (10° to 50° C)

Non-operating temperature -22° to 140° F (-30° to 60° C)

Operating humidity 10% to 90% (non-condensing at ambient)

Non-operating humidity 20% to 80% (non-condensing at ambient)

Operating shock N/A

Environmental

Non-operating shock

65 inch 2.9 ms, six surface; 30g 266 inch/second; 50g

266 inch/second six surface

Operating vibration 2-g peak acceleration

Non-operating vibration Starting at 5 Hz, vary the frequency of vibration from 5

to 500 Hz and back to 5 Hz at a Logarithmic sweep rate

of 1 octave per minute.

Drop (out of box) 26 in (66 cm) on carpet, six-drop sequence

Drop (in box) 29.93 in (76 cm) on concrete, 16-drop sequence

Approvals UL, FCC, CE Mark, TUV, TUV GS, VCCI, BSMI, C-Tick, KC

Ergonomic compliance ANSI HFS 100, ISO 9241-4, and TUVGS

HP USB (Grey) Business Slim Keyboard

Physical characteristics Keys 104, 105, 106, 107, 109 layout (depending upon country)

Dimensions (L x W x H) 17.19 x 5.41 x 0.82 in (43.68±1.5 x 13.76±1.0 x 2.1 ±1.0 cm)

Weight 1.32 lb (0.6± 0.08 kg)

Electrical Operating voltage + 4.4 - 5.25VDC

Power consumption 100-mA maximum (with 5 VDC power supplied and three LEDs ON)

System interface USB Type A plug connector
ESD Contact Discharge: 4, 6, 8 KV
EMI - RFI Air Discharge: 8, 10, 12 KV / 15 KV

Microsoft PC 99 - 2001 Conforms to FCC rules for a Class B computing device; Functionally

compliant

Mechanical Keycaps Low-profile design

Switch actuation Rubber dome + membrane

Switch life 10 million
Switch type Rubber dome
Key-leveling mechanisms Link bar

Cable length For all double-wide and greater-length keys

Microsoft PC 99 - 2001 Yes

Environmental Acoustics 55-dBA maximum sound pressure level

Operating temperature 10°C to 50°

Technical Specifications - Input/Output Devices

-30°C to 90° Non-operating

temperature

Operating humidity 10% to 90% (non-condensing at ambient) Non-operating humidity 60% to 80% (non-condensing at ambient)

Operating shock 40 g, six surfaces Non-operating shock 80 g, six surfaces Operating vibration 2-g peak acceleration Non-operating vibration 4-g peak acceleration

Drop (out of box) 26 in (66 cm) on carpet, six-drop sequence Drop (in box) 30 in (76.2 cm) on concrete, 16-drop sequence

FCC; CE; VCCI; BSMI; KC; EAC; RCM; TUV-GS; UL; RoHS; WEEE **Approvals**

Ergonomic compliance ANSI HFS 100; ISO 9241-4; and TUVGS

171.97 x 68.35 x 8.27 in (436.8± 1.5 x 137.6± 1.0 x Dimensions (LxWxH)

21.0± 1.0 cm)

Keyboard Weight - Without Two AA 1.23 lb (560± 80 g)

Alkaline Batteries

Dimensions (H x L x W) 1.46 x 4.53 x 2.47 in (37 x 115 x 62.9 mm)

Mouse Weight - Without Two AA 0.15 lb (67 g)

Alkaline Batteries

Dimensions (H x L x W) 0.33x 1.79 x 0.72 in (8.4 x 45.5 x 18.4 mm)

Weight 0.21 oz (5.9 g)

Receiver Cable Length - Minimum 6 ft (1.8 m)

> 32.8 ft (10 m) Range

Available USB port for the receiver

CD-ROM Drive

System Requirements *This system may require upgraded and/or separately purchased hardware and/or a DVD

drive to install the Windows 7 software and take full advantage of Windows 7

functionality. See http://www.microsoft.com/windows/windows-7/ for details.

Technical Specifications - Input/Output Devices

Product Safety UL; CSA /TUV (Europe only); CE Mark; CB Report

Ergonomics ANSI; ISO (Europe only); GS Mark (Germany only)

EMC FCC; CE; ACA (-tick); BSMI; KC; VCCI

CE Mark EN 55022:2010; EN 55024; EN 301489-1; EN 61000

Design Guidelines for PCs PC 99 - connector overmold colors; PC 2001 - full

functionality

Telecom All local telecom requirements and approvals for

intended markets

USA FCC Title 47 CFR, Par 15, Subpart C; other local

requirements

Country Support US, Belgium, Switzerland, Spain, Denmark, Netherlands,

France, Germany, Italy, Portugal, Sweden, Norway, Finland, UK, Poland, Czech Republic, Turkey, Greece, Austria, Bulgaria, Cyprus, Estonia, Hungary, Ireland, Latvia, Lithuania, Luxemburg, Malta, Romania, Slovakia,

Slovenia, Vietnam, HK, Australia, NZ, Malaysia, Singapore, Indonesia, Philippines, Thailand, Canada, China, Japan, Korea, Taiwan, India, Venezuela, Ecuador, Russia, Ukraine, Israel, Croatia, United Arab Emirates, Peru, Brazil, Chile, Argentina, Mexico, South Africa, and

up to 193 countries worldwide.

Environmental Keyboard contains 25% post-consumer recycled plastic material.

HP PS/2 Mouse

Dimensions 1.46 x 2.48 x 4.53 in (3.70 x 6.29 x 11.50 cm)

 $(H \times L \times W)$

Approvals

Weight 3.53 oz (100g; +10g/- 5 g)

Operating temperature -32° to 104°F (0° to 40° C)

Non-operating temperature -4° to 140°F (-20° to 60° C)

Operating humidity 10% to 90%

(non condensing at ambient)

Non-operating humidity 10% to 90%

(non condensing at ambient)

Environmental

Operating shock 40 g, 6 surfaces

Non-operating shock 80 g, 6 surfaces

Operating vibration 2 g peak acceleration

Non-operating vibration 4 g peak acceleration

Drop 80 cm height onto asphalt tile over concrete or equivalent, 5-

(out of box) drop in 5 direction except the cable face

Operating voltage 5 VDC ± 10%

Power consumption 100mA

Technical Specifications - Input/Output Devices

System consumption PS/2 mini-din connector **Electrical**

ESD CE level 4, 15 kV air discharge

EMI-RFI Conforms to FCC rules for a Class B computing device

Microsoft PC99 - 2001 Functionally compliant

Resolution 800 DPI

Tracking speed 10 in/s (25.4 cm/s) maximum

Acceleration ±15%

Switch actuation 65±20 gf

Mechanical Switch life 3,000,000 operations (using Hasco modified tester)

Switch type Low force micro-switches

Tracking mechanism life 80 km

Cable length 6 ft (1.8 m)

Microsoft PC99 - 2001 Mechanically compliant

Width 6 mm

Diameter $22.5 \pm 0.2 \text{ mm}$

Maximum rotation force 50 gf-cm

Switch type Light force micro-switch

Switch life 1 million operations

Mechanical life Minimum 200,000 revolutions

Regulatory Approvals UL/cUL, FCC, CE Mark, TUV/GS, VCCI, KCC, BSMI, C-Tick

HP USB 1000dpi Laser Mouse

Dimensions 1.47 x 4.53 x 2.47 in (37.3 x 114.97 x 62.86 mm)

 $(H \times L \times W)$

Scroll wheel

Weight 3.360 oz (102g)

Cable length 70.9 in (180 cm)

System requirements Available USB port

Environmental Operating Temperature 32° to 104° F (0° to 40° C)

Non-operating Temperature -4° to 140° F (-20° to 60° C)

Operating Humidity 10% to 90%

(non-condensing at ambient)

Mechanical Resolution 1000dpi

Tracking Speed 45 cm/sec

Cable Length 70.9 in (180 cm)

Scroll wheel

Technical Specifications - Input/Output Devices

HP USB PS/2 Washable Mouse

Dimensions $(H \times L \times W)$ 1.56 x 2.44 x 4.61 in (3.95 x 6.21 x 11.7 cm)

Weight 4.44 oz (126 g)

Environmental Operating temperature -32° to 104°F (0° to 40° C)

Non-operating

-4° to 140°F (-20° to 60° C) temperature

Operating humidity 10% to 90% (non-condensing at ambient)

Non-operating humidity 10% to 90% (non condensing at ambient)

Operating shock 40 g, 6 surfaces Non-operating shock 80 g, 6 surfaces

Operating vibration 2 g peak acceleration Non-operating vibration 4 g peak acceleration

80 cm height onto asphalt tile over concrete or equivalent, 5-drop in 5 Drop (out of box)

direction except the cable face

Electrical Operating voltage 5 VDC ± 10%

> **Power consumption** 100mA

System consumption PS/2 mini-din connector

ESD CE level 4, 15 kV air discharge

Conforms to FCC rules for a Class B computing device EMI-RFI

Microsoft® PC99 - 2001 Functionally compliant

400 ± 20% DPI Mechanical Resolution

> Tracking speed 10 in/s (25.4 cm/s) maximum

Acceleration 100 in/s/s (2.54 m/s/s) Switch actuation 61 g nominal peak force

Switch life 3,000,000 operations (using Hasco modified tester)

Switch type Low force micro-switches

Tracking mechanism life 155 mi (250 km) at average speed of 10 in/s

Cable length 6 ft (1.8 m)

Microsoft PC99 - 2001 Mechanically compliant Width 8 mm

Diameter 1.01 in (25.6 mm)

Maximum rotation speed 48 rats/sec

Switch type Light force micro-switch Switch life 1 million operations

Mechanical life Minimum 200,000 revolutions

Compliant UL, CSA, FCC, CE Mark, TUV, TUV GS, VCCI, BSMI, C-Tick, MIC **Regulatory approvals**

Technical Specifications – Input/Output Devices

HP USB Hardened Mouse

Mouse Type Wired optical mouse

Interface USB 2.0

Dimensions 114.97 x 62.92 x 37.3 mm (+/-0.3 mm)

 $(H \times L \times W)$ (11.49 x 6.29 x 1.46 in)

Weight 92 g (+/-10 g)

(3.2 oz)

Cable length 1.8 M

Tracking X-Y Positioning X-Y Wheel 1000 DPI

Resolution

Tracking Up to 30 in/sec in either X or Y direction

Speed

Z Axis Wheel Z Wheel 24 counts per revolution

Revolution

Tracking 0 ~ 120 rpm

Speed

Environmental Operating temperature 0° - 40°C

Non-operating -40° - 65°C

temperature

Operating humidity 90%
Agency Approvals CE
FCC

RCM VCCI EMC EAC BSMI UL

ICES-003 Class B

KCC TUV/GS

Electrical Input Voltage & Current 4.4 ~ 5.25 VDC / 100 mA

Power Consumption Under nominal 5 VDC power supplied, max current consumption is 100mA

with tracking speed up to 30 in/sec

Color Black

System requirements Windows 10, Windows 8.1 32/64bit, Windows 7 32/64bit

Technical Specifications – Input/Output Devices

HP Grey V2 Mouse

Dimensions 1.46 x 4.53 x 2.48 in (3.72 x 11.5 x 6.29 cm) ±1 mm

 $(H \times L \times W)$

Weight 3.53 oz (100g; +10g/- 5 g)

Operating temperature 50° to 122°F (10° to 50° C)

Non-operating temperature -22° to 140°F (-30° to 60° C)

Operating humidity 10% to 90%

(non condensing at ambient)

Non-operating humidity 20% to 80%

Environmental (non condensing at ambient)

Operating shock 40 g, 6 surfaces

Non-operating shock 80 g, 6 surfaces

Operating vibration 2 g peak acceleration

Non-operating vibration 4 g peak acceleration

Operating voltage 4.75~5.25 Vdc **Electrical**

Power consumption (typical) 10mA

Connector USB 2.0

Type 3D mouse (3 keys and wheel)

Resolution 800 DPI

MechanicalSensorPixArt vendor Optical USB mouse sensor. DIP

Tracking speed 30 inch/sec (max)

Tracking acceleration 8G(max), 1G=9.8m/s2

Cable length 6 ft (1.8 m)

Color Grey

FCC, CE, ICES, C-TICK, VCCI, KCC, BSMI, ISO9241, Part 4, Computer Work Station Ergonomics

Regulatory Approvals compliance, IEC 801-2, IEC 1000-4-2, EN 55024:1998 + A1:2001 + A2:2003, European

Standard EN 55022: 2006 Class B, CE Mark

HP USB Mouse

Dimensions 2.5 x 4.5 x 1.5 in (63.5 x 114.3 x 38.1 mm)

 $(H \times L \times W)$

Weight 0.22 lb (99.79 g)

Color Black

Connector USB

MechanicalResolution800 DPI sensitivity

Buttons Two primary buttons and clickable scroll wheel

Technical Specifications - Miscellaneous Features

MISCELLANEOUS FEATURES

Management Features

- Advanced Configuration and Power Management Interface (ACPI). Allows the system to wake from a low power mode.
 Controls system power consumption, making it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system.
- Intel® Wired for Management support; industry wide initiative to make Intel® architecture based PCs, servers and mobile computers more inherently manageable out-of-the-box and over the network
- Dual State Power Button; acts as both an on/off button and a suspend-to-sleep button

Serviceability Features

- Dual colored power LED on front of computer to indicate either normal or fault condition
- Diagnostic LED Explanation Table:
 - O Power LED will blink red 2 to 5 times, then blink white 2 or more times, then repeat (with beep tones for each blink initially):
 - 2 red + 2 white User must provide file for BIOS recovery (USB storage typically)
 - 2 red + 3 white User must enter a key sequence to proceed with recovery by policy
 - 2 red + 4 white BIOS recovery is in progress
 - 3 red + 2 white Memory could not be initialized
 - 3 red + 3 white Graphics adapter could not be found
 - 3 red + 4 white Power supply failure / not connected
 - 3 red + 5 white Processor not installed
 - 3 red + 6 white Current processor does not support an enabled feature
 - 4 red + 2 white Processor has exceeded its temperature threshold / system thermal shutdown
 - 4 red + 3 white System internal temperature has exceeded its threshold
 - 5 red + 2 white System controller firmware is not valid
 - 5 red + 3 white System controller detected BIOS is not executing
 - 5 red + 4 white BIOS could not complete initialization / PCA failure
 - 5 red + 5 white System controller rebooted the system after a health or recovery timer triggered
- HP PC Hardware Diagnostics UEFI:
 - O This utility enables hardware level testing outside the operating system on many components. The diagnostics can be invoked by pressing F2 at POST, and is available as a download from http://hp.com/go/techcenter/pcdiags
- System/Emergency ROM
- Flash ROM
- CMOS Battery Holder for easy replacement
- BIOS recovery files are maintained on the local OS drive when updating with HP BIOS Update and Recovery utility (HPBIOSUPDREC)
- 5 Aux Power LED on System PCA
- Processor ZIF Socket for easy Upgrade
- Over-Temp Warning on Screen (Requires IM Agents)
- Clear Password Jumper
- DIMM Connectors for easy Upgrade
- Clear CMOS Button
- NIC LEDs (integrated) (Green & Amber)
- Dual Color Power and HD LED To Indicate Normal Operations and Fault Conditions
- Color coordinated cables and connectors
- Front power switch
- System memory can be upgraded without removing the system board or any internal components
- CD & Diskette Removal
- Tool icon for easy Identification

Technical Specifications – Miscellaneous Features

ADDITIONAL FEATURES

Description

Driv	e L	ock

Implementation of the industry standard ATA Security feature set. When enabled, it prevents software access to user data on the drive until one or two user-defined passwords are provided.

Boot Sectors Protection

Drive Protection System

MBR or GPT boot sectors of the hard drive are critical to securely starting the operating system. By saving the MBR or GPT data (depending on the how the OS was installed), the BIOS will be able to monitor for changes and allow the user to override them with the backup copy at boot-up.

DPS Access through F10 Setup during Boot

A diagnostic hard drive self-test. It scans critical physical components and every sector of the hard drive for physical faults and then reports any faults to the user Running independently of the operating system, it can be accessed through a Windows-based diagnostics utility or through the computer's setup procedure. It produces an evaluation on whether the hard drive is the source of the problem and needs to be replaced

The system expands on the Self-Monitoring, Analysis, and Reporting Technology (SMART), a continuously running systems diagnostic that alerts the user to certain types of failures

SMART Technology (Self-Monitoring, Analysis and Reporting Technology) Allows hard drives to monitor their own health and to raise flags if imminent failures were predicted

SMART I - Drive Failure Prediction

SMART II - Off-Line Data Collection

Predicts failures before they occur. Tracks fault prediction and failure indication parameters such as re-allocated sector count, spin retry count, calibration retry count

SMART III - Off-Line Read Scanning with Defect Reallocation By avoiding actual hard drive failures, SMART hard drives act as "insurance" against unplanned user downtime and potential data loss from hard drive failure

SMART IV - End-to-End CRC for hard

drives

Detects errors in Read/Write buffers on HDD cache RAM

IOEDC: I/O Error Detection Circuitry

Interface in F10 setup provides confirmation of SMART IV support.

After-Market Options (availability may vary by region)

	400 G3	400 G4	400 G4	480 G4	Part
Business Monitors (sample list)*	DM	SFF	MT	MT	Number
HP ProDisplay P240va 23.8-inch Monitor	x	x	x	×	N3H14AA
HP ProDisplay P232 23-inch Monitor	x	x	X	x	K7X31AA
HP ProDisplay P222c 21.5-inch Video Conferencing Monitor	X	X	X	X	L4J08AA
*Additional models are available.					
	400 G3	400	400 G4	480 G4	Part
Communication Devices	DM	G4SFF	MT	MT	Number
Intel® Ethernet I210 - T1 Gbe NIC		X	X	X	E0X95AA
Intel® 7265 802.11ac 2x2 DualBand Combo PCIe x1 Card		X	X	X	N4G85AA
	400 G3	400 G4	400 G4	480 G4	Part
Graphics Solutions	DM	SFF	MT	MT	Number
NVIDIA® GeForce® GT 730 2GB DP PCIe		X	x	x	Z9H51AA
x8 Card AMD® Radeon? R7 450 4GB PCIe x16 Card			x	x	Z9H52AA
HP UHD USB Graphics Adapter	x	X	x	x	N2U81AA
HP DisplayPort? Cable Kit	X	X	X	x	VN567AA
HP DisplayPort? To DVI-D Adapter	X	X	x	x	FH973AA
HP DisplayPort? To VGA Adapter	X	X	x	x	AS615AA
HP DisplayPort? To HDMI 4k Adapter	X	X	x	x	K2K92AA
HP DVI to DVI Cable	X	X	x	x	DC198A
HP (Bulk) 700mm DisplayPort? Cable Kit	X	X	X	X	V8Y77A6
	400 G3	400 G4	400 G4	480 G4	Part
Data Storage Drives	DM	SFF	MT	MT	Number
HP 500GB 7200PRM SATA 6.0Gb/s 3.5" ? Hard Drive		X	x	x	QK554AA
HP 1TB 7200rpm SATA 6Gb/s 3.5"? Hard Drive		x	x	×	QK555AA
HP 256GB SATA TLC Solid State Drive	X	X	x	x	P1N68AA
HP 512GB Turbo Drive G2 TLC M.2 SSD Drive	X	X	X	X	X8U75AA
HP 9.5mm Slim Removable SATA 500GB		X	X	Х	T7G14AA
HP 256GB SATA Non-SED Solid State Drive	X	X	X	X	WOU55AA
HP 9.5mm G3 8/4 SFF G4 400 SFF/MT DVD-Writer		X	X	X	1CA53AA
Input Devices	400 G3 DM	400 G4 SFF	400 G4 MT	480 G4 MT	Part Number
HP Conferencing Keyboard	Х	Х	Х	х	K8P74AA
HP USB Business Slim Keyboard	X	X	x	x	N3R87AA
HP PS/2 Business Slim Keyboard	x	X	x	x	N3R86AA

After-Market Options (availability may vary by region)

HP Wireless Business Slim Keyboard and Mouse**	X	x	x	X	QY449AA
HP USB Business Slim Grey Keyboard (EMEA only)	X	X	X	X	Z9H49AA
HP USB Business Slim Smart Card CCID Keyboard	x	X	X	X	Z9H48AA
HP USB PS/2 Washable Keyboard and Mouse Kit**	X	X	X	X	BU207AA
HP USB Grey V2 Mouse (EMEA only)	X	X	X	x	Z9H74AA
HP USB Business Slim Keyboard and Mouse (China Only)	×	X	x	X	Z9H50AA
HP USB Hardened Mouse	X	X	X	x	P1N77AA
HP PS/2 Mouse (Expansion module required for use with DM)	×	X	x	X	QY775AA
HP USB Mouse	X	X	X	X	QY777AA
HP USB 1000dpi Laser Mouse	X	X	X	X	QY778AA

^{**} Keyboard contains 25% post-consumer recycled plastic material

		400 G3	400 G4	400 G4	480 G4	Part
Desktop Mini Accessories		DM	SFF	MT	MT	Number
	HP Desktop Mini DVD Super Multi-	X				K9Q83AA
	Writer ODD Expansion Module					
	HP Desktop Mini 500GB HDD/ I/O	X				K9Q82AA
	Expansion Module					
	HP Desktop Mini Rack Mount Tray Kit	X				G1K21AA
	HP Desktop Mini Security/Dual VESA	X				G1K22AA
	Sleeve					
	HP Desktop Mini 65W Power Supply Kit	X				L2X04AA
	HP Desktop Mini 90W Power Supply Kit	X				L4R65AA
	HP Desktop Mini Vertical Chassis Stand	X				G1K23AA
	HP Desktop Mini Lock Box	X				P1N78AA
	HP Desktop Mini Port Cover Kit	X				P3R65AA
	HP Desktop Mini I/O Expansion Module	X				K9Q84AA
	HP Integrated Work Center Desktop	X				G1V61AA
	Mini/Thin Clients					
	HP Single Monitor Arm	X				BT861AA
	HP Quick Release Bracket	X				EM870AA
	HP PC Mounting Bracket for Monitors	X				N6N00AT
	•					

		400 G3	400 G4	400 G4	480 G4	Part
Sys	tem Memory	DM	SFF	MT	MT	Number
	HP 4GB DDR4-2400 DIMM		X	X	x	Z9H59AA
	HP 8GB DDR4-2400 DIMM		x	X	x	Z9H60AA
	HP 16GB DDR4-2400 DIMM		x	X	x	Z9H57AA
	HP 4GB DDR4-2400 SODIMM	x				Z9H55AA
	HP 8GB DDR4-2400 SODIMM	x				Z9H56AA
	HP 16GB DDR4-2400 SODIMM	x				Z9H53AA

After-Market Options (availability may vary by region)

		400 G3	400 G4	400 G4	480 G4	Part
Mul	timedia Devices	DM	SFF	MT	MT	Number
	HP Business Headset v2	X	X	X	X	T4E61AA
	HP USB Business Speakers v2	X	X	X	X	N3R89AA
		400 G3	400 G4	400 G4	480 G4	Part
Sec	urity Devices	DM	SFF	MT	MT	Number
	HP Business PC Security Lock v2 Kit		X	X	X	N3R93AA
	HP Keyed Cable Lock 10mm Kit	X	X	X	X	T1A62AA
	HP Dual Head Keyed Cable Lock Kit	X	X	X	X	T1A64AA
		400 G3	400 G4	400 G4	480 G4	Part
Sta	nds and Accessories	DM	SFF	MT	MT	Number
	HP (10) 400 G4 600/800 G3 SFF G4 MT		X	X		Z9H64A6
	Bezel Support Kit					
	HP Single Monitor Arm	X	X	X	x	BT861AA

LANDesk Software (E-Delivery)*

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^{*}Optional and sold separately.

Change Log

Date of change:	Version History:	Action	Description of change:
January 25, 2017	Version 1 to 2	Launch	QS launched
February 13, 2017	Version 2 to 3	Update	Graphics Section updated
March 2, 2017	Version 3 to 4	Update	Accessories Section updated (added accessory), Environmental
			Section updated (added Environmental data)
March 6, 2017	Version 4 to 5	Update	Storage section updated
March 9, 2017	Version 5 to 6	Update	After market section updated (added accessory)
March 21, 2017	Version 6 to 7	Update	Environmental Section updated
April 5, 2017	Version 7 to 8	Update	Dimensions nomenclature updated (W x D x H)
April 17, 2017	Version 8 to 9	Deleted	I/O devices from Features section
April 20, 2017	Version 9 to 10	Update	Slots section updated
April 27, 2017	Version 10 to 11	Update	Graphics section updated
May 9, 2017	Version 11 to 12	Update	Network/Communications updated (Intel® 3168 802.11AC 1x1 Wi-
			Fi +Bluetooth? M.2 Combo Card non-VPro)
May 24, 2017	Version 12 to 13	Update	Integrated Graphics table updated (replaced by PM request)